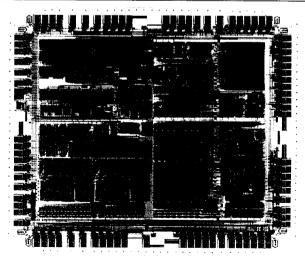


80C188EB-16, -13, -8 16-BIT HIGH-INTEGRATION EMBEDDED PROCESSOR

- Full Static Operation
- True CMOS Inputs and Outputs
- - 40°C to +85°C Operating Temperature Range
 - Low System Cost 8-Bit Interface
- Integrated Feature Set
 - Low-Power Static CPU Core
 - Two Independent UARTs each with an Integral Baud Rate Generator
 - Two 8-Bit Multiplexed I/O Ports
 - Programmable Interrupt Controller
 - Three Programmable 16-Bit Timer/Counters
 - Clock Generator
 - Ten Programmable Chip Selects with Integral Wait-State Generator
 - Memory Refresh Control Unit
 - System Level Testing Support (ONCE™ Mode)
- Direct Addressing Capability to 1 Mbyte Memory and 64 Kbyte I/O
- Speed Versions Available:
 - 16 MHz (80C188EB-16)
 - 13 MHz (80C188EB-13)
 - 8 MHz (80C188EB-8)

- **■** Low-Power Operating Modes:
 - Idle Mode Freezes CPU Clocks but keeps Peripherals Active
 - Powerdown Mode Freezes All Internal Clocks
- Complete System Development Support
 - ASM86 Assembler, PL/M 86, Pascal 86, Fortran 86, C-86, and System Utilities
 - In-Circuit Emulator (ICETM-188EB)
- Available In:
 - 80-Pin Quad Flat Pack (TS80C188EB)
 - 84-Pin Plastic Leaded Chip Carrier (TN80C188EB)

The 80C188EB is a second generation CHMOS High-Integration microprocessor. It has features that are new to the 80C188 family and include a STATIC CPU core, an enhanced Chip Select decode unit, two independent Serial Channels, I/O ports, and the capability of Idle or Powerdown low power modes.



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May 1991 Order Number: 270885-002

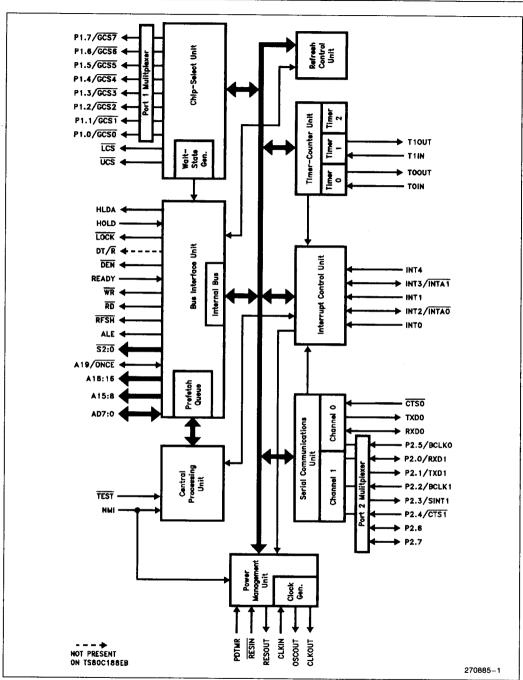


Figure 1. 80C188EB Block Diagram



INTRODUCTION

The 80C188EB is the first product in a new generation of low-power, high-integration microprocessors. It enhances the existing 186 family by offering new features and new operating modes. The 80C188EB is object code compatible with the 80C186/80C188 microprocessors. The 80C188EB has an 8-bit external data bus but still retains a 16-bit internal bus. An 8-bit external bus reduces system cost by requiring that only single byte-wide memories be used.

The feature set of the 80C188EB meets the needs of low power, space critical applications. Low-Power applications benefit from the static design of the CPU core and the integrated peripherals. Minimum current consumption is achieved by providing a Powerdown mode that halts operation of the device, and freezes the clock circuits. Peripheral design enhancements ensure that non-initialized peripherals consume little current.

Space critical applications benefit from the integration of commonly used system peripherals. Two serial channels are provided for services such as diagnostics, inter-processor communication, modern interface, terminal display interface, and many others. A flexible chip select unit simplifies memory and peripheral interfacing. The interrupt unit provides sources for up to 129 external interrupts and will prioritize these interrupts with those generated from the on-chip peripherals. Three general purpose timer/counters and sixteen multiplexed I/O port pins round out the feature set of the 80C188EB.

OVERVIEW

Figure 1 shows a block diagram of the 80C188EB. The Execution Unit (EU) is an enhanced 8088 CPU core that includes: dedicated hardware to speed up effective address calculations, enhance execution speed for multiple-bit shift and rotate instructions and for multiply and divide instructions, string move instructions that operate at full bus bandwidth, ten new instruction, and full static operation. The Bus Interface Unit (BIU) is the same as that found on the original 188 family products, except the queuestatus mode has been deleted and buffer interface control has been changed to ease system design timings. An independent internal bus is used to allow communication between the BIU and internal peripherals.

80C188EB Core Architecture

REGISTER SET

The 8086, 8088, 80186, 80188, 80C186, and 80C188 all contain the same basic set of registers, instructions, and addressing modes. The 80C188EB is upward compatible with all of these microprocessors.

The 80C188EB base architecture has fourteen 16-bit registers as shown in Figure 2. There are eight general purpose registers which may be used for arithmetic and logic operands. Four of these registers (AX, BX, CX, and DX) can be used as 16-bit registers or split into pairs of separate 8-bit registers. The other four registers (BP, SI, DI, and SP) may also be used to determine offset addresses of operands in memory. These registers may contain base addresses or indexes to particular locations within a segment. The addressing mode selects the specific registers for operand and address calculations.

Another four 16-bit registers (CS, DS, ES, SS) select the segments of memory that are immediately addressable for code, stack, and data. There are two remaining special purpose registers (IP and F) that record or alter certain aspects of the 80C188EB processor state.

	15	0	_
	AH	AL	AX
	BH	BL	BX
	СН	CL	CX
ŀ	DH	DL	DX
	Source	e Index	SI
	Destinat	ion Index	DI
	Base I	Pointer	BP
	Stack Pointer		SP
	Code Segment		cs
	Stack Segment		SS
-	Data S	egment	DS
	Extra Segment		ES
1			
	Instruction Pointer		IP
	Flags		F
l			

Figure 2, 80C188EB Register Set

INSTRUCTION SET

The instruction set is divided into seven categories: data transfer, arithmetic, shift/rotate/logical, string manipulation, control transfer, high-level instructions, and processor control. These categories are summarized in Figure 4.

An 80C188EB instruction can reference anywhere from zero to several operands. An operand can reside in a register, in the instruction itself, or in memory.

MEMORY ORGANIZATION

Memory is organized in sets of segments. Each segment is a linear contiguous sequence of up to 64K (2¹⁶) 8-bit bytes. Memory is addressed using a two-component address (a pointer) that consists of a 16-bit base segment and a 16-bit offset. The 16-bit base segment values are contained in one of four internal segment registers (code, data stack, extra). The physical address is calculated by shifting the base value left by four bits and adding the 16-bit offset value to yield a 20-bit physical address (see Figure 3). The resulting 20-bit address allows for a 1 Mbyte address range.

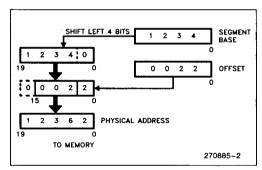


Figure 3. Two Component Address

All instructions that address operands in memory must specify the base segment and the 16-bit offset value. For speed and compact instruction encoding, the segment register used for a physical address generation is implied by the addressing mode used (see Table 1). Special segment override instruction prefixes allow the implicit segment register selection rules to be overridden for special cases. The code, stack, data, and extra segments may coincide for simple programs.

Table 1. Segment Register Selection Rules

Memory Reference Needed	Segment Register Used	Implicit Segment Selection Rule
Instructions	Code (CS)	Instruction prefetch and immediate data
Stack	Stack (SS)	All stack pushes and pops; any memory references which use the BP register as a base
External	Extra (ES)	All String instruction references which use the DI register as an index
Local Data	Data (DS)	All other data references

ADDRESSING MODES

The 80C188EB provides eight categories of addressing modes to specify operands. Two addressing modes are provided for instructions that operate on register or immediate operands:

- Register Operand Mode: The operand is located in one of the 8- or 16-bit general registers.
- Immediate Operand Mode: The operand is included in the instruction.

Six modes are provided to specify the location of an operand in a memory segment. A memory operand address consists of two 16-bit components: a segment base and an offset. The segment base is supplied by a 16-bit segment register either implicitly chosen by the addressing mode or explicitly chosen by a segment override prefix. The offset, also called the effective address, is calculated by summing any combination of the following three address elements:

- the displacement (an 8- or 16-bit immediate value contained in the instruction);
- the base (contents of either the BX or BP base registers); and
- the index (contents of either the SI or DI index registers).



GENERAL PURPOSE	DIVISION	NO OPERATION
MOV	DIV	NOP
PUSH	IDIV	1401
POP	AAD	MICH I EVEL INCTRUCTIONS
PUSHA	CBW	HIGH LEVEL INSTRUCTIONS
POPA		
	CWD	ENTER
XCHG		LEAVE
XLAT	STRING OPERATIONS	BOUND
INPUT/OUTPUT	MOVS INS	CONDITIONAL TRANSFERS
IN	· · · · ·	
****	OUTS	JA/JNBE
OUT	CMPS	JAE/JNB
	SCAS	JB/JNAE
ADDRESS OBJECT	LODS	JBE/JNA
	STOS	JC
LEA		
LDS	REP	JE/JZ
	REPE/REPZ	JG/JNLE
LES	REPNE/REPNZ	JGE/JNL
		JL/JNGE
FLAG TRANSFER	LOGICALS	JLE/JNG
	LOGICALS	
LAHF	410-	JNC
- · · ·	NOT	JNE/JNZ
SAHF	AND	JNO
PUSHF	OR	JNP/JP0
POPF	XOR	JNS
	TEST	**·*
ADDITION	1551	JO_
ADDITION	•••	JP/JPE
A 5mm	SHIFTS	JS
ADD		
INC	SHL/SAL	UNCONDITIONAL TRANSFERS
AAA	SHR	CHOCKET THAT
DAA	SAR	CALL
	SAN	CALL
SUBSTRACTION		RET
SUBSTRACTION	ROTATES	JMP
SUB	ROL	ITERATION CONTROLS
SBB	ROR	TIENATION CONTROLS
DEC		
	RCL	LOOP
NEG	RCR	LOOPE/LOOPZ
CMP		LOOPNE/LOOPNZ
AAS	FLAG OPERATIONS	JCXZ
DAS		UOAL
	STC	INTERRUPTS
MULTIPLICATION	CLC	IN I ENNUP 15
	_ _	·
A.41.41	CMC	INT
MUL	STD	INTO
IMUL	CLD	IRET
AAM	STI	
•	CLI	
	EXTERNAL	
	SYNCHRONIZATION	
	HLT	
	WAIT	
	LOCK	
	2001	

Figure 4. 80C188EB Instruction Set

Any carry out from the 16-bit addition is ignored. 8-bit displacements are sign extended to 16-bit values.

Combinations of these three address elements define the six memory addressing modes, described below.

- · Direct Mode: The operand's offset is contained in the instruction as an 8- or 16-bit displacement el-
- · Reaister Indirect Mode: The operand's offset is in one of the registers SI, DI, BX, or BP.
- · Based Mode: The operand's offset is the sum of an 8- or 16-bit displacement and the contents of a base register (BX or BP).
- Indexed Mode: The operand's offset is the sum of an 8- or 16-bit displacement and the contents of an index register (SI or DI).
- · Based Indexed Mode: The operand's offset is the sum of the contents of a base register and an index register.
- Based Indexed Mode with Displacement: The operand's offset is the sum of a base register's contents, an index register's contents, and an 8- or 16-bit displacement.

DATA TYPES

The 80C188EB directly supports the following data types:

- Integer: A signed binary numeric value contained in an 8-bit byte or 16-bit word. All operations assume a 2's complement representation. Signed 32- and 64-bit integers are supported using the 80C187 Numerics Coprocessor.
- · Ordinal: An unsigned binary numeric value contained in an 8-bit byte or 16-bit word.
- Pointer: A 16- or 32-bit quantity, composed of a 16-bit offset component, or a 16-bit segment base component and a 16-bit offset component.
- String: A contiguous sequence of bytes or words. A string may contain from 1 Kbyte to 64 Kbytes.
- ASCII: A byte representation of alphanumeric and control characters using the ASCII standard of character representation.

- BCD: A byte (unpacked) representation of the decimal digits 0-9.
- Packed BCD: A byte (packed) representation of two decimal digits (0-9). One digit is stored in each nibble (4 bits) of the byte.

In general, individual data elements must fit within defined segment limits.

INTERRUPTS

An interrupt transfers execution to a new program location. The old program address (CS:IP) and machine state (F) are saved on the stack to allow resumption of the interrupted program. Interrupts fall into three classes: hardware initiated, software (program) initiated, and instruction exception initiated. Hardware initiated interrupts occur in response to an external or internal input and are classified as nonmaskable or maskable.

Programs may cause an interrupt by executing the "INT" instruction. Instruction exceptions occur when an illegal opcode has been fetched into the queue and is read by the execution unit. Another type of exception can be generated when executing an "ESC" instruction.

For all cases except the "ESC" exception, the return address from an exception will point at the instruction immediately following the instruction causing the exception. The return address after an "ESC" exception will point back to the ESC instruction causing the exception, or to the segment override prefix immediately preceding the ESC instruction if the prefix was present.

A table containing up to 256 pointers defines the proper interrupt service routine for each interrupt. Interrupts 0-31 are reserved by intel. Table 2 shows the 80C188EB predefined type and default priority levels. For each interrupt, an 8-bit vector (Vector Type) identifies the appropriate table entry. Multiplying the 8-bit vector by 4 defines the vector address. INT instructions contain or imply the vector type and allow access to all 256 interrupts.

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Table 2. 80C188EB Interrupt Vectors

Interrupt Name	Vector Type	Vector Address	Default Priority	Related Instructions
Divide Error	0	00H	1	DIV, IDIV
Single Step Interrupt	1	04H	1A	All
Non-Maskable Interrupt	2	08H	1	INT 2 or NMt
One Byte Interrupt	3	0CH	1	INT
Interrupt on Overflow	4	10H	1	INTO
Array Bounds Check	5	14H	1	BOUND
Invalid OP-Code	6	18H	1 .	Illegal Inst
ESC OP-Code Interrupt	. 7	1CH	1	ESC OP-Codes
Timer 0 Interrupt	8	20H	2	
Reserved	9-11	24H-2CH		
INT0 Interrupt	12	30H	5	
INT1 Interrupt	- 13	34H	6	
INT2 Interrupt	14	38H	7	
INT3 Interrupt	15	3CH	8	
Reserved	16	40H		
INT4 Interrupt	17	44H	4	
Timer1 Interrupt	18	48H	2A	
Timer2 Interrupt	19	4CH	2B	
UART 0 Receive Interrupt	20	50H	3	
UART 0 Transmit Interrupt	21	54H	3A	
Reserved	22-31	58H-7CH		

BUS INTERFACE UNIT

The 80C188EB core incorporates a bus controller that generates local bus control signals. In addition, it employs a HOLD/HLDA protocol to share the local bus with other bus masters.

The bus controller is responsible for generating 20 bits of address, read and write strobes, bus cycle status information, and data (for write operations) information. It is also responsible for reading data off the local bus during a read operation. A READY input pin is provided to extend a bus cycle beyond the minimum four states (clocks).

A HOLD/HLDA protocol is provided by the local bus controller to allow multiple bus masters to share the same local bus. When the 80C188EB relinquishes control of the local bus, it floats certain bus control signals to allow another bus master to drive these pins directly. Refer to the Pin Description section to determine which pins the 80C188EB will float during a HOLD/HLDA bus exchange.

The 80C188EB local bus controller also generates two control signals (DEN and DT/R) when interfacing to external transceiver chips. (Both DEN and DT/R are available on the TN80C188EB device, only DEN is available on the TS80C188EB device.) This capability allows the addition of transceivers for simple buffering of the mulitplexed address/data bus.

CLOCK GENERATOR

The 80C188EB provides an on-chip clock generator for both internal and external clock generation. The clock generator features a crystal oscillator, a divideby-two counter, and two low-power operating modes.

The oscillator circuit is designed to be used with either a parallel resonant fundamental or third-overtone mode crystal network. Alternatively, the oscillator circuit may be driven from an external clock source. Figure 5 shows the various operating modes of the 80C188EB oscillator circuit.

The crystal or clock frequency chosen must be twice the required processor operating frequency due to the internal divide-by-two counter. This counter is used to drive all internal phase clocks and the external CLKOUT signal. CLKOUT is a 50% duty cycle processor clock and can be used to drive other system components. All A.C. timings are referenced to CLKOUT.

The following parameters are recommended when choosing a crystal:

Temperature Range: **Application Specific** ESR (Equivalent Series Resistance): 40Ω max C0 (Shunt Capacitance of Crystal): 7.0 pF max C_L (Load Capacitance): 20 pF ± 2 pF Drive Level: 1 mW max

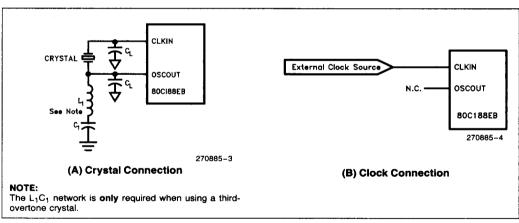


Figure 5. 80C188EB Clock Configurations



80C188EB Peripheral Architecture

The 80C188EB has integrated several common system peripherals with a CPU core to create a compact, yet powerful system. The integrated peripherals are designed to be flexible and provide logical interconnections between supporting units (e.g., the interrupt control unit supports interrupt requests from the timer/counters or serial channels).

The list of integrated peripherals include:

- 7-Input Interrupt Control Unit
- 3-Channel Timer/Counter Unit
- 2-Channel Serial Communications Unit
- 10-Output Chip-Select Unit
- I/O Port Unit
- · Refresh Control Unit
- Power Management Unit

The registers associated with each integrated periheral are contained within a 128 x 16 register file called the Peripheral Control Block (PCB). The PCB can be located in either memory or I/O space on any 256 Byte address boundary. During bus cycles that access the PCB, the bus controller will signal the operation externally (i.e., the RD, WR, status, address, data, etc., lines will be driven as in a normal bus cycle). However, READY is ignored and the contents of the data bus during a read operation is ignored. When using any of the internal registers (AX, BX, etc.) as the source of data to be moved into a PCB register, it is recommended that a byte operation be specified. Since the 80C188EB retains a 16-bit internal bus architecture, all byte write operations to the PCB registers will result in word operation. If immediate data is used, then a word write must be specified.

The starting address of the PCB is controlled by a relocation register and can overlap any of the memory or I/O regions programmed into the Chip Select Unit. In this case, the overlapped chip select will not go active when the PCB is read or written.

Figure 6 provides a list of the registers associated with the PCB. The Register Bit Summary at the end of this specification individually lists all of the registers and identifies each of their programming attributes.

INTERRUPT CONTROL UNIT

The 80C188EB can receive interrupts from a number of sources, both internal and external. The interrupt control unit serves to merge these requests, on a priority basis, for individual service by the CPU.

Each interrupt source can be independently masked by the Interrupt Control Unit (ICU) or all interrupts can be globally masked by the CPU.

Internal interrupt sources include the Timers and Serial channel 0. External interrupt sources come from the five input pins INT4:0. The NMI interrupt pin is not controlled by the ICU and is passed directly to the CPU. Although the Timer and Serial channel each have only one request input to the ICU, separate vector types are generated to service individual interrupts within the Timer and Serial channel units.

The 80C188EB ICU provides a mechanism for expanding the number of external interrupt sources. Two pairs of pins can be independently configured to support an external slave interrupt controller (82C59A). Each pair of external pins can be expanded to support 64 interrupts, making it possible for the 80C188EB to support a total of 129 external interrupts.

The ICU may be used in a polled mode if interrupts are undesirable. When polling, the processor disables interrupts and then polls the ICU whenever it is convenient.

TIMER/COUNTER UNIT

The 80C188EB Timer/Counter Unit (TCU) provides three 16-bit programmable timers. Two of these are highly flexible and are connected to external pins for control or clocking. A third timer is not connected to any external pins and can only be clocked internally. However, it can be used to clock the other two timer channels. The TCU can be used to count external events, time external events, generate non-repetitive waveforms, generate timed interrupts. etc.

Each timer has at least one 16-bit compare register and one 16-bit count register. Timers 0 and 1 each have an additional 16-bit compare register. The count register is incremented every fourth CPU clock cycle (internal clocking), every time Timer2 expires (Timers 0 and 1 only), or every Low-to-High transition on the timer input pin (Timers 0 and 1 only). The input clock to Timers 0 and 1 must not exceed one fourth the operating frequency of the 80C188EB. When the count register matches the value programmed into the compare register, several operations may happen.

All three timers can generate an interrupt when the compare register matches the value in the count register. Additionally, Timers 0 and 1 have an output pin that can change state or pulse when the compare condition occurs.

PCB Offset	Function		PCB Offset	Function
00Н	Reserved		40H	Timer2 Count
02H	End Of Interrupt		42H	Timer2 Compare
04H	Poli		44H	Reserved
06H	Poll Status		46H	Timer2 Control
08H	Interrupt Mask		48H	Reserved
0AH	Priority Mask		4AH	Reserved
0CH	In-Service		4CH	Reserved
0EH	Interrupt Request		4EH	Reserved
10H	Interrupt Status		50H	Reserved
12H	Timer Control		52H	Port0 Pin
14H	Serial Control		54H	Port0 Control
16H	INT4		56H	Port0 Latch
18H	INT0 Control	1	58H	Port1 Direction
1AH	INT1 Control		5AH	Port1 Pin
1CH	INT2 Control		5CH	Port1 Control
1EH	INT3 Control		5EH	Port1 Latch
20H	Reserved		60H	Serial0 Baud
22H	Reserved		62H	Serial0 Count
24H	Reserved		64H	Serial0 Control
26H	Reserved		66H	Serial0 Status
28H	Reserved		68H	Serial0 RBUF
2AH	Reserved		6AH	Serial0 TBUF
2CH	Reserved		6CH	Reserved
2EH	Reserved		6EH	Reserved
30H	Timer0 Count		70H	Serial1 Baud
32H	Timer0 Compare A		72H	Serial1 Count
34H	Timer0 Compare B		74H	Serial1 Control
36H	Timer0 Control		76H	Serial1 Status
38H	Timer1 Count		78H	Serial1 RBUF
ЗАН	Timer1 Compare A		7AH	Serial1 TBUF
зсн	Timer1 Compare B		7CH	Reserved
зЕН	Timer1 Control		7EH	Reserved

PCB Offset	Function
80H	GCS0 Start
82H	GCS0 Stop
84H	GCS1 Start
86H	GCS1 Stop
88H	GCS2 Start
8AH	GCS2 Stop
8CH	GCS3 Start
8EH	GCS3 Stop
90H	GCS4 Start
92H	GCS4 Stop
94H	GCS5 Start
96H	GCS5 Stop
98H	GCS6 Start
9AH	GCS6 Stop
9CH	GCS7 Start
9EH	GCS7 Stop
A0H	LCS Start
A2H	LCS Stop
A4H	UCS Start
A6H	UCS Stop
A8H	Relocation
AAH	Reserved
ACH	Reserved
AEH	Reserved
вон	Refresh Base
В2Н	Refresh Time
В4Н	Refresh Control
В6Н	Refresh Address
вен	Power Control
ВАН	Reserved
всн	Step tD
BEH	Reserved

PCB Offset	Function
C0H	Reserved
C2H	Reserved
C4H	Reserved
C6H	Reserved
C8H	Reserved
CAH	Reserved
CCH	Reserved
CEH	Reserved
DOH	Reserved
D2H	Reserved
D4H	Reserved
D6H	Reserved
D8H	Reserved
DAH	Reserved
DCH	Reserved
DEH	Reserved
E0H	Reserved
E2H	Reserved
E4H	Reserved
E6H	Reserved
E8H	Reserved
EAH	Reserved
ECH	Reserved
EEH	Reserved
F0H	Reserved
F2H	Reserved
F4H	Reserved
F6H	Reserved
F8H	Reserved
FAH	Reserved
FCH	Reserved

FEH

Reserved

Figure 6. 80C188EB Peripheral Control Block Registers



Other timer programming options include:

- All three timers can be set to halt or continue after a compare match.
- Timers 0 and 1 can be reset or retriggered using their respective input pins.
- TCU registers can be read or written at any time.

SERIAL COMMUNICATIONS UNIT

The Serial Control Unit (SCU) of the 80C188EB contains two independent channels. Each channel is identical in operation except that only channel 0 is supported by the integrated interrupt controller (channel 1 has an external interrupt pin). Each channel has its own baud rate generator that is independent of the Timer/Counter Unit, and can be internally or externally clocked up at one half the 80C188EB operating frequency.

Each serial channel supports one synchronous and four asynchronous modes of operation and is compatible with the serial ports of the MCS®-51 and MCS®-96 family of products. Data field length can be 7-, 8-, or 9-bits with optional odd or even parity (generated and checked) and one stop bit (generated and checked). The 9-bit mode has an optional "addressing" feature to simplify interprocessor communication. Each serial port is doubled buffered in both transmit and receive operation (data can be read or written to a buffer register while data is shifted into or out of a shifting register, respectively).

A Clear-To-Send input pin can be programmed to prevent data transmission if the pin is sampled inactive. Serial channel 0 is supported by the integrated interrupt controller, providing separate receive and transmit vector types. Serial channel 1 has an external interrupt pin which OR's the receive and transmit interrupts. This external interrupt pin can be routed to either the external pins of the ICU, the NMI pin, or any other external system interrupt controller. Status bits are provided to allow polling of the serial channels if interrupts are not desired.

Independent baud rate generators are provided for each of the serial channels. For the asynchronous modes, the generator supplies an 8x baud clock to both the receive and transmit register logic. A 1x baud clock is provided in the synchronous mode.

Additional features of the SCU include:

- Framing error, receive buffer overrun error, and parity error detection.
- Break detect.
- Break send.

CHIP-SELECT UNIT

The 80C188EB Chip-Select Unit (CSU) integrates logic which provides up to ten programmable chipselects to access both memories and peripherals. In addition, each chip-select can be programmed to automatically insert additional clocks (wait-states) into the current bus cycle and automatically terminate a bus cycle independent of the condition of the READY input pin.

Each of the chip-selects can be programmed to go active for either memory or I/O accesses. UCS is the only chip-select that is active after a reset and is enabled for memory addresses in the range 0FFC00H to 0FFFFH (this allows a boot-ROM to be accessed using UCS). Every chip-select has a programmable start and stop register that defines the active region for the chip-select, and the ready characteristics for the region.

The start and stop address fields are 10 bits in length and are matched against the upper 10 bits of either the memory or I/O address. A 10-bit compare results in a granularity of 1 Kbytes for memory accesses and 64 bytes for I/O accesses. Each chip select can be disabled by programming its start address greater than its stop address or by clearing its enable bit.

Each chip-select can be programmed to automatically insert wait-states, and to control whether the external READY input is to be ignored or used. The 80C188EB bus controller will wait the programmed number of wait-states before the external READY pin can be used to extend or terminate the bus cycle.

Overlapping of chip-selects is allowed. However, each one that overlaps will go active. If any overlapping chip-select has been programmed to use external ready, the bus control unit will insert the least amount of programmed wait-states programmed before the external ready pin is used. If all overlapped chip-selects ignore external ready, the bus controller will insert the maximum number of programmed wait-states. Any chip-select that overlaps the Peripheral Control Block (PCB) will not go active for that portion of the address range allocated to the PCB.

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The Generic Chip-Selects (GCS7:0) are multiplexed with an output only Port function. Any channel that is being used as a chip-select must be disabled as a port pin by correctly programming the port pin control registers (see the following section).

I/O PORT UNIT

The I/O Port Unit (IPU) on the 80C188EB supports two 8-bit channels of input, output, or input/output operation. Port 1 is multiplexed with the chip select pins and is output only. Most of Port 2 is multiplexed with the serial channel pins. Port 2 pins are limited to either an output or input function depending on the operation of the serial pin it is multiplexed with.

Two bits of Port 2 are not multiplexed with any other peripheral functions and can be used as either an input or an output function. A port direction register is used to define the function of the port pin. The output for these two pins are open drain.

Besides a direction register, each port channel has a port latch register, port pin register, and a port multiplexer control register.

REFRESH CONTROL UNIT

The Refresh Control Unit (RCU) automatically generates a periodic memory read bus cycle to keep dynamic or pseudo-static memory refreshed. A 9-bit counter controls the number of clocks between refresh requests.

A 12-bit address generator is maintained by the RCU and is presented on the A12:1 address lines during the refresh bus cycle. The address generator is incremented only after the refresh bus cycle is run. This ensures that all address combinations will be presented to the memory array even if the refresh bus cycle is not run before another request is generated. Address bits A19:13 are programmable to allow the refresh address block to be located on any 8 Kbyte boundary.

The chip-select unit is active during refresh bus cycles. This means that a chip-select will go active if the refresh address is within the limits specified for the channel. In addition, AFSH is driven active to signal that a refresh bus cycle is in progress. Data on the AD7:0 bus is ignored.

A pending refresh request will attempt to abort a HOLD/HLDA bus exchange. HLDA is deasserted when a refresh request is pending and a bus HOLD is already in progress. HOLD must then be released in order for the 80C188EB to execute the refresh bus cycle.

POWER MANAGEMENT UNIT

The 80C188EB Power Management Unit (PMU) is provided to control the power consumption of the device. The PMU provides three power modes: Active, Idle, and Powerdown.

Active Mode indicates that all units on the 80C188EB are functional and the device consumes maximum power (depending on the level of peripheral operation). Idle Mode freezes the clocks of the Execution and Bus units at a logic zero state (all peripherals continue to operate normally). An unmasked interrupt, NMI, or reset will cause the 80C188EB to exit the Idle mode.

The Powerdown mode freezes all internal clocks at a logic zero level and disables the crystal oscillator. All internal registers hold their values provided $V_{\rm CC}$ is maintained. Current consumption is reduced to just transistor junction leakage. An NMI or processor reset will cause the 80C188EB to exit the Powerdown Mode. A timing pin is provided to establish the length of time between exiting Powerdown and resuming device operation. (Length of time depends on startup time of crystal oscillator and is application dependent.)

ONCETM Test Mode

To facilitate testing and inspection of devices when fixed into a target system, the 80C188EB has a test mode available which forces all output and input/output pins to be placed in the high-impedance state. ONCE stands for "ON Circuit Emulation". The ONCE mode is selected by forcing the A19/ONCE pin LOW (0) during a processor reset (this pin is weakly held to a HIGH (1) level while RESIN is active).



PACKAGE INFORMATION

This section describes the pins, pinouts, and thermal characteristics for the 80C188EB in the Plastic Leaded Chip Carrier (PLCC) package and Quad Flat Pack (QFP) package. For complete package specifications and information, see the Intel Packaging Outlines and Dimensions Guide (Order Number: 231369).

Pin Descriptions

The 80C188EB pins are described in this section. Table 3 presents the legend for interpreting the pin descriptions in Table 4. Figure 7 provides an example pin description entry. The "I/O" signifies that the pins are bidirectional (i.e., have both an input and output function). The "S" indicates that, as an input, the signal is synchronized to CLKOUT for proper operation. The "H(Z)" indicates that these pins will float while the processor is in the Hold Acknowledge state. R(Z) indicates that these pins will float while RESIN is low. P(X) Indicates that these pins will retain their current value when Idle or Powerdown Modes are entered.

All pins float while the processor is in the ONCETM Mode, except OSCOUT (OSCOUT is required for crystal operation).

Name	Туре	Description
AD7:0	I/O S(L) H(Z) R(Z) P(X)	These pins provide a multiplexed ADDRESS and DATA bus. During the address phase of the bus cycle, address bits 0 through 15 are presented on the bus and can be latched using ALE. 8-bit data information are transferred during the data phase of the bus cycle.

Figure 7. Example Pin Description Entry

Table 4. Pin Description Nomenclature

Symbol	Description
1	Input Only Pin
0	Output Only Pin
1/0	Pin can be either input or output
_	Pin "must be" connected as described
S()	Synchronous. Input must meet setup and hold times for proper operation of the processor. The pin is: S(E) edge sensitive S(L) level sensitive
A()	Asynchronous. Input must meet setup and hold only to guarantee recognition. The pin is: A(E) edge sensitive A(L) level sensitive
H()	While the processor's bus is in the Hold Acknowledge state, the pin: H(1) is driven to V _{CC} H(0) is driven to V _{SS} H(Z) floats H(Q) remains active H(X) retains current state
R()	While the processor's RES line is low, the pin: R(1) is driven to V _{CC} R(0) is driven to V _{SS} R(Z) floats R(WH) weak pullup R(WL) weak pulldown
P()	While Idle or Powerdown modes are active, the pin: P(1) is driven to V _{CC} P(0) is driven to V _{SS} P(Z) floats P(Q) remains active ⁽¹⁾ P(X) retains current state

NOTE:

 Any pin that specifies P(Q) are valid for Idle Mode. All pins are P(X) for Powerdown Mode.

Table 4. 80C188EB Pin Descriptions

Name	Туре	Description
Vcc		POWER connections consist of four pins which must be shorted externally to a V _{CC} board plane.
V _{SS}		GROUND connections consist of six pins which must be shorted externally to a V _{SS} board plane.
CLKIN	I A(E)	CLock Input is an input for an external clock. An external oscillator operating at two times the required 80C188EB operating frequency can be connected to CLKIN. For crystal operation, CLKIN (along with OSCOUT) are the crystal connections to an internal Pierce oscillator.
OSCOUT	O H(Q) R(Q) P(Q)	OSCIllator OUTput is only used when using a crystal to generate the external clock. OSCOUT (along with CLKIN) are the crystal connections to an internal Pierce oscillator. This pin is not to be used as 2X clock output for non-crystal applications (i.e., this pin is N.C. for non-crystal applications). OSCOUT does not float in ONCE mode.
CLKOUT	O H(Q) R(Q) P(Q)	CLock OUTput provides a timing reference for inputs and outputs of the processor, and is one-half the input clock (CLKIN) frequency. CLKOUT has a 50% duty cycle and transistions every falling edge of CLKIN.
RESIN	A(L)	RESet IN causes the 80C188EB to immediately terminate any bus cycle in progress and assume an initialized state. All pins will be driven to a known state, and RESOUT will also be driven active. The rising edge (low-to-high) transition synchronizes CLKOUT with CLKIN before the 80C188EB begins fetching opcodes at memory location 0FFFF0H.
RESOUT	O H(0) R(1) P(0)	RESet OUTput that indicates the 80C188EB is currently in the reset state. RESOUT will remain active as long as RESIN remains active.
PDTMR	I/O A(L) H(WH) R(Z) P(1)	Power-Down TIMeR pin (normally connected to an external capacitor) that determines the amount of time the 80C188EB waits after an exit from power down before resuming normal operation. The duration of time required will depend on the startup characteristics of the crystal oscillator.
NMI	I A(E)	Non-Maskable Interrupt input causes a TYPE-2 interrupt to be serviced by the CPU. NMI is latched internally.
TEST	I A(E)	TEST is used during the execution of the WAIT instruction to suspend CPU operation until the pin is sampled active (LOW).
AD7:0	1/O S(L) H(Z) R(Z) P(X)	These pins provide a multiplexed Address and Data bus. During the address phase of the bus cycle, address bits 0 through 7 are presented on the bus and can be latched using ALE. 8-bit data information is transferred during the data phase of the bus cycle.
A15:8	O H(Z) R(Z) P(X)	These pins provide Address information throughout the entire bus cycle.



Table 4. 80C188EB Pin Descriptions (Continued)

Name	Туре	Description	
A18:16 A19/ONCE	I/O H(Z) R(W1) P(X)	These pins provide multiplexed ADDRESS during the address phase of the bus cycle. Address bits 16 through 19 are presented on these pins and can be latched using ALE. These pins are driven to a logic 0 during the data phase of the bus cycle. During a processor reset (RESIN active), A19/ONCE is used to enable ONCE mode. A18:16 must not be driven low during reset or improper 80C188EB operation may result.	
S2:0	O H(Z) R(Z) P(1)	Bus cycle Status are encoded on these pins to provide bus transaction information. S2:0 are encoded as follows: S2 S1 S0 Bus Cycle Initiated	
ALE	O H(0) R(0) P(0)	Address Latch Enable output is used to strobe address information into a transparent type latch during the address phase of the bus cycle.	
RFSH	O H(Z) R(Z) P(1)	ReFreSH output signals that a refresh bus cycle is in progress.	
RD	O H(Z) R(Z) P(1)	ReaD output signals that the accessed memory or I/O device must drive data information onto the data bus.	
WR	O H(Z) R(Z) P(1)	WRIte output signals that data available on the data bus are to be written into the accessed memory or I/O device.	
READY	I A(L) S(L)	READY input to signal the completion of a bus cycle. READY must be active to terminate any 80C188EB bus cycle, unless it is ignored by correctly programming the Chip-Select Unit.	
DEN	O H(Z) R(Z) P(1)	Data ENable output to control the enable of bi-directional transceivers when buffering a 80C188EB system. DEN is active only when data is to be transferred on the bus.	

Table 4. 80C188EB Pin Descriptions (Continued)

Name	Туре	Description
DT/R	O H(Z) R(Z) P(X)	Data Transmit/Receive output controls the direction of a bi-directional buffer when buffering an 80C188EB system. DT/R is only available for the PLCC package (TN80C188EB).
LOCK	I/O H(Z) R(W1) P(1)	LOCK output indicates that the bus cycle in progress is not to be interrupted. The 80C188EB will not service other bus requests (such as HOLD) while LOCK is active. This pin is configured as a weakly held high input while RESIN is active and must not be driven low.
HOLD	I A(L)	HOLD request input to signal that an external bus master wishes to gain control of the local bus. The 80C188EB will relinquish control of the local bus between instruction boundaries not conditioned by a LOCK prefix.
HLDA	O H(1) R(0) P(0)	HoLD Acknowledge output to indicate that the 80C188EB has relinquish control of the local bus. When HLDA is asserted, the 80C188EB will (or has) floated its data bus and control signals allowing another bus master to drive the signals directly.
UCS	O H(1) R(1) P(1)	Upper Chip Select will go active whenever the address of a memory or I/O bus cycle is within the address limitations programmed by the user. After reset, UCS is configured to be active for memory accesses between 0FFC00H and 0FFFFFH.
<u>LCS</u>	O H(1) R(1) P(1)	Lower Chip Select will go active whenever the address of a memory bus cycle is within the address limitations programmed by the user. LCS is inactive after a reset.
P1.0/GCS0 P1.1/GCS1 P1.2/GCS2 P1.3/GCS3 P1.4/GCS4 P1.5/GCS5 P1.6/GCS6 P1.7/GCS7	O H(X)/H(1) R(1) P(X)/P(1)	These pins provide a multiplexed function. If enabled, each pin can provide a Generic Chip Select output which will go active whenever the address of a memory or I/O bus cycle is within the address limitations programmed by the user. When not programmed as a Chip-Select, each pin may be used as a general purpose output Port. As an output port pin, the value of the pin can be read internally.
T0OUT T1OUT	O H(Q) R(1) P(Q)	Timer OUTput pins can be programmed to provide a single clock or continuous waveform generation, depending on the timer mode selected.
TOIN T1IN	l A(L) A(E)	Timer INput is used either as clock or control signals, depending on the timer mode selected.



Table 4. 80C188EB Pin Descriptions (Continued)

Name	Туре	Description
INTO INT1 INT4	I A(E,L)	Maskable INTerrupt input will cause a vector to a specific Type interrupt routine. To allow interrupt expansion, INT0 and/or INT1 can be used with INTAO and INTAT to interface with an external slave controller.
INT2/INTAO INT3/INTAT	I/O A(E,L) /H(1) R(Z) /P(1)	These pins provide a multiplexed function. As inputs, they provide a maskable INTerrupt that will cause the CPU to vector to a specific Type interrupt routine. As outputs, each is programmatically controlled to provide an INTERRUPT ACKNOWLEDGE handshake signal to allow interrupt expansion.
P2.7 P2.6	I/O A(L) H(X) R(Z) P(X)	BI-DIRECTIONAL, open-drain Port pins.
CTSO P2.4/CTS1	l A(L)	Clear-To-Send input is used to prevent the transmission of serial data on their respective TXD signal pin. CTS1 is multiplexed with an input only port function.
TXD0 P2.1/TXD1	O H(X)/H(Q) R(1) P(X)/P(Q)	Transmit Data output provides serial data information. TXD1 is multiplexed with an output only Port function. During synchronous serial communications, TXD will function as a clock output.
RXD0 P2.0/RXD1	I/O A(L) R(Z) H(Q) P(X)	Receive Data input accepts serial data information. RXD1 is multiplexed with an input only Port function. During synchronous serial communications, RXD is bi-directional and will become an output for transmission or data (TXD becomes the clock).
P2.5/BCLK0 P2.2/BCLK1	A(L)/A(E)	Baud CLock input can be used as an alternate clock source for each of the integrated serial channels. BCLKx is multiplexed with an input only Port function, and cannot exceed a clock rate greater than one-half the operating frequency of the 80C188EB.
P2.3/SINT1	O H(X)/H(Q) R(0) P(X)/P(Q)	Serial INTerrupt output will go active to indicate serial channel 1 requires service. SINT1 is multiplexed with an output only Port function.

80C188EB PINOUT

Tables 5 and 6 list the 80C188EB pin names with package location for the 84-pin Plastic Leaded Chip Carrier (PLCC) component. Figure 8 depicts the complete 80C188EB pinout (PLCC package) as viewed from the top side of the component (i.e., contacts facing down).

Tables 7 and 8 list the 80C188EB pin names with package location for the 80-pin Quad Flat Pack (QFP) component. Figure 9 depicts the complete 80C188EB (QFP package) as viewed from the top side of the component (i.e., contacts facing down).

Table 5. PLCC Pin Names with Package Location

Address/Data Bus		
Name	Location	
AD0	61	
AD1	66	
AD2	68	
AD3	70	
AD4	72	
AD5	74	
AD6	76	
AD7	78	
A8	62	
A9	67	
A10	69	
A11	71	
A12	73	
A13	75	
A14	77	
A15	79	
A16	80	
A17	81	
A18	82	
A19/ONCE	83	

Bus Control			
Name	Location		
ALE	6		
RFSH	7		
<u>50</u>	10		
<u>S1</u>	9		
S2	8		
RD	4		
WR	5		
READY	18		
DEN	11		
DT/R	16		
LOCK	15		
HOLD	13		
HLDA	12		

Power		
Name	Location	
V _{SS}	2, 22, 43, 63, 65, 84	
V_{CC}	1, 23, 42, 64	

	Processor Control		
	Name	Location	
	RESIN	37	
	RESOUT	38	
	CLKIN	41	
	OSCOUT	40	
	CLKOUT	44	
	TEST	14	
	NC	60	
	NC	39	
	NC	3	
	PDTMR	36	
ļ	NMI	17	
	INTO	31	
	INT1	32	
Ì	INT2/INTA0	33	
ı	INT3/INTA1	34	
	INT4	35	

1/0		
Name	Location	
UCS	30	
<u>LCS</u>	29	
P1.0/GCS0	28	
P1.1/GCS1	27	
P1.2/GCS2	26	
P1.3/GCS3	25	
P1.4/GCS4	24	
P1.5/GCS5	21	
P1.6/GCS6	20	
P1.7/GCS7	19	
T0OUT	45	
TOIN	46	
T1OUT	47	
T1IN	48	
RXD0	53	
TXD0	52	
P2.5/BCLK0	54	
CTS0	51	
P2.0/RXD1	57	
P2.1/TXD1	58	
P2.2/BCLK1	59	
P2.3/SINT1	55	
P2.4/CTS1	56	
P2.6	50	
P2.7	49	

Table 6. PLCC Package Locations with Pin Name

Location	Name
1	v _{cc}
2	V _{SS}
3	NC
4	RD
5	WR
6	ALE
7	RFSH
8	<u>52</u>
9	<u>S1</u>
10	SO
11	DEN
12	HLDA
13	HOLD
14	TEST
15	LOCK
16	DT/R
17	NMI
18	READY
19	P1.7/GCS7
20	P1.6/GCS6
21	P1.5/GCS5

fable 6. PLCC Package Location				
ocation	Name		Loca	
22	V _{SS}		43	
23	Vcc		44	
24	P1.4/GC\$4		45	
25	P1.3/GCS3		46	
26	P1.2/GCS2		47	
27	P1.1/GCS1		48	
28	P1.0/GCS0		49	
29	LCS		50	
30	UCS		51	
31	INT0		52	
32	INT1		50	
33	INT2/INTAO		54	
34	INT3/INTA1		55	
35	INT4		56	
36	PDTMR		57	
37	RESIN		58	
38	RESOUT		59	
39	NC		60	
40	OSCOUT		6	
41	CLKIN		6	
42	Vcc		6:	

ocations with Pin Name		
Location	Name	
· 43	V _{SS}	
44	CLKOUT	
45	TOOUT	
46	TOIN	
47	T10UT	
48	T1IN	
49	P2.7	
50	P2.6	
51	CTS0	
52	TXD0	
53	RXD0	
54	P2.5/BCLK0	
55	P2.3/SINT1	
56	P2.4/CTS1	
57	P2.0/RXD1	
58	P2.1/TXD1	
59	P2.2/BCLK1	
60	NC	
61	AD0	
62	A8	
63	Vss	

Location	Name
64	Vcc
65	Vss
66	AD1
67	A9
68	AD2
69	A10
70	AD3
71	A11
72	AD4
73	A12
74	AD5
75	A13
76	AD6
77	A14
78	AD7
79	A15
80	A16
81	A17
82	A18
83	A19/ONCE
84	Vec

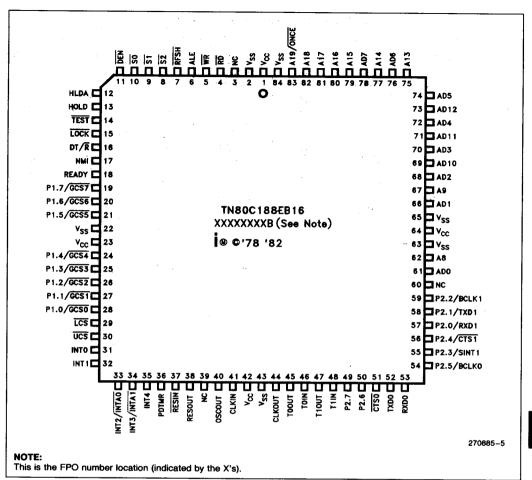


Figure 8. 84-Pin Plastic Leaded Chip Carrier Pinout Diagram

Table 7. QFP Pin Name with Package Location

Address/Data Bus		
Name	Location	
AD0	10	
AD1	15	
AD2	17	
AD3	19	
AD4	21	
AD5	23	
AD6	25	
AD7	27	
A8	11	
A9	16	
A10	18	
A11	20	
A12	22	
A13	24	
A14	26	
A15	28	
A16	29	
A17	30	
A18	31	
A19/ONCE	32	

Table 1: QLT THE Hall		
Bus Control		
Name	Location	
ALE	38	
RFSH	39	
<u>50</u>	42	
<u>81</u>	41	
<u>\$2</u>	40	
RD	36	
WR	37	
READY	49	
DEN	43	
LOCK	47	
HOLD	45	
HLDA	44	

Processor Control				
Name	Location			
RESIN	68			
RESOUT	69			
CLKIN	71			
OSCOUT	70			
CLKOUT	74			
TEST	46			
PDTMR	67			
NMI	48			
INT0	62			
INT1	63			
INT2/INTAO	64			
INT3/INTA1	65			
INT4	66			

Power				
Name Location				
V _{SS}	12, 14, 33, 35, 53, 73			
Vcc	13, 34, 54, 72			

1/0				
Name	Location			
UCS	61			
LCS	60			
P1.0/GCS0	59			
P1.1/GCS1	58			
P1.2/GCS2	57			
P1.3/GCS3	56			
P1.4/GCS4	55			
P1.5/GCS5	52			
P1.6/GCS6	51			
P1.7/GCS7	50			
TOOUT	75			
TOIN	76			
T1OUT	77			
T1IN	78			
RXD0	3			
TXD0	2			
P2.5/BCLK0	4			
CTS0	1			
P2.0/RXD1	7			
P2.1/TXD1	8			
P2.2/BCLK1	9			
P2.3/SINT1	5			
P2.4/CTS1	6			
P2.6	80			
P2.7	79			

Table 8. QFP Package Location with Pin Names

Location	N
Location	Name
1	CTS0
2	TXD0
3	RXD0
4	P2.5/BCLK0
5	P2.3/SINT1
6	P2.4/CTS1
7	P2.0/RXD1
8	P2.1/TXD1
9	P2.2/BCLK1
10	AD0
11	A8
12	V _{SS}
13	Vcc
14	V _{SS}
15	AD1
16	A9
17	AD2
18	A10
19	AD3
20	A11

Table 8. QFP Package				
Location	Name			
21	AD4			
22	A12			
23	AD5			
24	A13			
25	AD6			
26	A14			
27	AD7			
28	A15			
29	A16			
30	A17			
31	A18			
32	A19/ONCE			
33	V _{SS}			
34	Vcc			
35	V _{SS}			
36	RD			
37	WR			
38	ALE			
39	RFSH			
40	<u>\$2</u>			

	The state of the s				
Locat	lon	Name			
41		S1			
42		<u>\$0</u>			
43		DEN			
44		HLDA			
45		HOLD			
46		TEST			
47		LOCK			
48		NMI			
49	ĺ	READY			
50		P1.7/GCS7			
51		P1.6/GCS6			
52		P1.5/GCS5			
53		V _{SS}			
54		V _{CC}			
55		P1.4/GCS4			
56	- 1	P1.3/GCS3			
57	ŀ	P1.2/GCS2			
58		P1.1/GCS1			
59	ĺ	P1.0/GCS0			
60		<u>LCS</u>			

Location	Name
61	UCS
62	INTO
63	INT1
64	INT2/INTA0
65	INT3/INTA1
66	INT4
67	PDTMR
68	RESIN
69	RESOUT
70	OSCOUT
71	CLKIN
72	Vcc
73	V _{SS}
74	CLKOUT
75	TOOUT
76	TOIN
77	T1OUT
78	T1IN
79	P2.7
80	P2.6

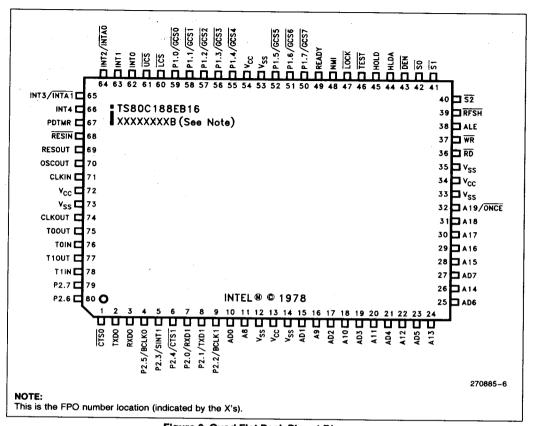


Figure 9. Quad Flat Pack Pinout Diagram

PACKAGE THERMAL SPECIFICATIONS

The 80C188EB is specified for operation when T_C (the case temperature) is within the range of $-40^{\circ}C$ to $+100^{\circ}C$ (PLCC package) or $-40^{\circ}C$ to $+114^{\circ}C$ (QFP package). T_C may be measured in any environment to determine whether the 80C188EB is within the specified operating range. The case temperature must be measured at the center of the top surface.

 T_A (the ambient temperature) can be calculated from θ_{CA} (thermal resistance from the case to ambient) with the following equation:

Typical values for θ_{CA} at various airflows are given in Table 9 for the 84-pin Plastic Leaded Chip Carrier (PLCC) package.

Table 10 shows the maximum T_A allowable (without exceeding T_C) at various airflows and operating frequencies. P (the maximum power consumption, specified in watts) is calculated by using the maximum ICC as tabulated in the DC specifications and V_{CC} of 5V.

 $T_A = T_C - P^*\theta_{CA}$

Table 9. Thermal Resistance (θ_{CA}) at Various Airflows (in °C/Watt)

		Airflow Linear ft/min (m/sec)					
	0 (0)	200 (1.01)	400 (2.03)	600 (3.04)	800 (4.06)	1000 (5.07)	
θ_{CA} (PLCC)	30	24	21	19	17	16.5	
θ _{CA} (QFP)	58	47	43	40	38	36	

Table 10. Maximum T_A at Various Airflows (in °C)

		Airflow Linear ft/min (m/sec)					
	Τŗ	0	200	0 400	600	800	1000
	(MHz)	(0)	(1.01)	(2.03)	(3.04)	(4.06)	(5.07)
TA (PLCC)	16	91.5	93.5	94	94.5	95.5	95.5
	26	88.5	91	92	92.5	93.5	93.5
	32	85	87.5	89.5	90.5	91.5	92
T _A (QFP)	16	98	101	102	103	103.5	104
İ I	26	92	96	97.5	99	99.5	100
	32	85	90.5	92.5	94	95	96

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ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings

Parameter	Maximum Rating
Storage Temperature	-65°C to +150°C
Case Temp Under Bias	-65°C to +120°C
Supply Voltage with respect to V _{SS}	0.5V to +6.5V
Voltage on other Pins	

with respect to $V_{SS} \dots -0.5V$ to $V_{CC} + 0.5V$

NOTICE: This data sheet contains information on products in the sampling and initial production phases of development. It is valid for the devices indicated in the revision history. The specifications are subject to change without notice.

*WARNING: Stressing the device beyond the "Absolute Maximum Ratings" may cause permanent damage. These are stress ratings only. Operation beyond the "Operating Conditions" is not recommended and extended exposure beyond the "Operating Conditions" may affect device reliability.

OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Units
V _{CC}	Supply Voltage	4.5	5.5	٧
T _F	Input Clock Frequency 80C188EB-16	0	32	MHz
	80C188EB-13	0	26.08	MHz
	80C188EB	0	16	MHz
T _C	Case Temperature Under Bias TN80C188EB-XX (PLCC)	-40	+ 100	°C
	TS80C188EB-XX (QFP)	-40	+114	°C

RECOMMENDED CONNECTIONS

Power and ground connections must be made to multiple V_{CC} and V_{SS} pins. Every 80C188EB-based circuit board should include separate power (V_{CC}) and ground (V_{SS}) planes. Every V_{CC} pin must be connected to the power plane, and every V_{SS} pin must be connected to the ground plane. Pins identified as "NC" must not be connected in the system. Liberal decoupling capacitance should be placed near the 80C188EB. The processor can cause transient power surges when its output buffers transition, particularly when connected to large capacitive loads.

Low inductance capacitors and interconnects are recommended for best high frequency electrical performance. Inductance is reduced by placing the decoupling capacitors as close as possible to the 80C188EB $V_{\rm CC}$ and $V_{\rm SS}$ package pins.

Always connect any unused input to an appropriate signal level. In particular, unused interrupt inputs (INT0:4) should be connected to V_{CC} through a pull-up resistor (in the range of 50 K Ω). Leave any unused output pin or any NC pin unconnected.

TARGETED DC SPECIFICATIONS

Symbol	Parameter	Min	Max	Units	Notes
V _{IL}	Input Low Voltage	-0.5	0.3*V _{CC}	v	
V _{IH}	Input High Voltage	0.7*V _{CC}	V _{CC} + 0.5	V	
VOL	Output Low Voltage		0.45	٧	I _{OL} = 3 mA (Min)
V _{OH}	Output High Voltage	V _{CC} - 0.5		٧	$I_{OH} = -2 \text{ mA (Min)}$
V _{HYR}	Input Hysterisis on RESIN	0.50		٧	
I _{LI1}	Input Leakage Current for pins: AD7:0, READY, HOLD, RESIN, CLKIN, TEST, NMI, INT4:0, TOIN, T1IN, RXD0, BCLK0, CTS0, RXD1, BCLK1, CTS1, P2.6, P2.7		±15	μΑ	0V ≤ V _{IN} ≤ V _{CC}
I _{LI2}	Input Leakage Current for pins: A19/ONCE, A18:16, LOCK	-0.275	-5.0	mA	V _{IN} = 0.7 V _{CC} (Note 1)
LO •	Output Leakage Current		± 15	μΑ	0.45 ≤ V _{OUT} ≤ V _{CC} (Note 2)
lcc	Supply Current Cold (RESET) 80C188EB-16	,	90	mA	(Note 3)
,	80C188EB-13		73	mA	(Note 3)
	80C188EB-8		45	mA	(Note 3)
IID	Supply Current Idle 80C188EB-16		63	mA	(Note 4)
:	80C188EB-13		48	mA	(Note 4)
	80C188EB-8		31	mA	(Note 4)
lPD	Supply Current Powerdown 80C188EB-16		100	μΑ	(Note 5)
	80C188EB-13		100	μΑ	(Note 5)
	80C188EB-8		100	μΑ	(Note 5)
CIN	Input Pin Capacitance	0	15	рF	T _F = 1 MHz
COUT	Output Pin Capacitance	0	15	pF	T _F = 1 MHz (Note 6)

- 1. These pins have an internal pull-up device that is active while RESIN is low and ONCE Mode is not active. Sourcing more current than specified (on any of these pins) may invoke a factory test mode.
- 2. Tested by outputs being floated by invoking ONCE Mode or by asserting HOLD.
- 2. Tested by duputs being noticed by invoking office induce of by asserting notice.

 3. Measured with the device in RESET and at worst case frequency, V_{CC}, and temperature with ALL outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or V_{SS}.

 4. Measured with the device in HALT (IDLE Mode active) and at worst case frequency, V_{CC}, and temperature with ALL outputs loaded as specified in AC Test Conditions, and all floating outputs driven to V_{CC} or V_{SS}.
- 5. Measured with the device in HALT (Powerdown Mode active) and at worst case frequency, VCC, and temperature with ALL outputs loaded as specified in AC Test Conditions, and all floating outputs driven to VCC or VSS.
- 6. Output Capacitance is the capacitive load of a floating output pin.



ICC VERSUS FREQUENCY AND VOLTAGE

The current (I_{CC}) consumption of the 80C188EB is essentially composed of two components; I_{PD} and I_{CCS} .

I_{PD} is the **quiescent** current that represents internal device leakage, and is measured with all inputs or floating outputs at GND or V_{CC} (no clock applied to the device). I_{PD} is equal to the Powerdown current and is typically less than 50 μ A.

 I_{CCS} is the **switching** current used to charge and discharge parasitic device capacitance when changing logic levels. Since I_{CCS} is typically much greater than I_{PD} , I_{PD} can often be ignored when calculating I_{CC} .

 I_{CCS} is related to the voltage and frequency at which the device is operating. It is given by the formula:

$$\begin{array}{lll} \text{Power} &= \text{V} \times \text{I} = \text{V}^2 \times \text{C}_{\text{DEV}} \times \text{f} \\ \therefore \text{I} &= \text{I}_{\text{CC}} = \text{I}_{\text{CCS}} = \text{V} \times \text{C}_{\text{DEV}} \times \text{f} \end{array}$$

Where: $V = Device operating voltage (V_{CC})$

 C_{DEV} = Device capacitance f = Device operating frequency

 $I_{CCS} = I_{CC} = Device current$

Measuring C_{DEV} on a device like the 80C188EB would be difficult. Instead, C_{DEV} is calculated using the above formula by measuring I_{CC} at a known V_{CC} and frequency (see Table 11). Using this C_{DEV} value, I_{CC} can be calculated at any voltage and frequency within the specified operating range.

EXAMPLE: Calculate the typical I_{CC} when operating at 10 MHz, 4.8V.

$$I_{CC} = I_{CCS} = 4.8 \times 0.583 \times 10 \approx 28 \text{ mA}$$

PDTMR PIN DELAY CALCULATION

The PDTMR pin provides a delay between the assertion of NMI and the enabling of the internal clocks when exiting Powerdown. A delay is required only when using the on-chip oscillator to allow the crystal or resonator circuit time to stabilize.

NOTE:

The PDTMR pin function does not apply when RESIN is asserted (i.e., a device reset during Powerdown is similar to a cold reset and RESIN must remain active until after the oscillator has stabilized).

To calculate the value of capacitor required to provide a desired delay, use the equation:

$$440 \times t = C_{PD}$$
 (5V, 25°C)

Where: t = desired delay in seconds

C_{PD} = capacitive load on PDTMR in microfarads

EXAMPLE: To get a delay of 300 μ s, a capacitor value of $C_{PD}=440\times(300\times10^{-6})=0.132~\mu\text{F}$ is required. Round up to standard (available) capacitive values.

NOTE:

The above equation applies to delay times greater than 10 μ s and will compute the **TYPICAL** capacitance needed to achieve the desired delay. A delay variance of +50% or -25% can occur due to temperature, voltage, and device process extremes. In general, higher V_{CC} and/or lower temperature will decrease delay time, while lower V_{CC} and/or higher temperature will increase delay time.

Table 11, Device Capacitance (Cnev) Values

Parameter	Тур	Max	Units	Notes		
C _{DEV} (Device in Reset)	0.583	1.02	mA/V*MHz	1, 2		
C _{DEV} (Device in Idle)	0.408	0.682	mA/V*MHz	1, 2		

^{1.} Max C_{DEV} is calculated at -40° C, all floating outputs driven to V_{CC} or GND, and all outputs loaded to 50 pF (including CLKOUT and OSCOUT).

^{2.} Typical C_{DEV} is calculated at 25°C with all outputs loaded to 50 pF except CLKOUT and OSCOUT, which are not loaded.



AC SPECIFICATIONS

AC Characteristics—80C188EB-16

Symbol	Parameter	Min	Max	Units	Notes
INPUT CL	OCK			-	110100
T _F	CLKIN Frequency	0	32	MHz	
Tc	CLKIN Period	31.25	∞ ∞	ns	1 1
<u>Т</u> сн	CLKIN High Time	10	∞	ns	1, 2
TCL	CLKIN Low Time	10	∞	ns	1, 2
TCR	CLKIN Rise Time	1	8	ns	1, 3
T _{CF}	CLKIN Fall Time	11	8	ns	1,3
OUTPUT					
TCD	CLKIN to CLKOUT Delay	0	20	ns	1, 4
Ţ	CLKOUT Period		2*T _C	ns	'i'
T _{PH}	CLKOUT High Time	(T/2) - 5	(T/2) + 5	ns	1
T _{PL} T _{PR}	CLKOUT Low Time	(T/2) - 5	(T/2) + 5	ns	1
'PR T _{PF}	CLKOUT Rise Time CLKOUT Fall Time	1	6	ns	1,5
		11	6	ns	1, 5
OUTPUT					
T _{CHOV1}	ALE, <u>S2:0, DEN, DT/R, RFSH,</u> LOCK, A19:16	3	22	ns	1, 4, 6, 7
T _{CHOV2}	GCS0:7, LCS, UCS, RD, WR	3	27	ns	1, 4, 6, 8
T _{CLOV1}	RFSH, DEN, LOCK, RESOUT, HLDA, TOOUT, T1OUT, A19:16	3	22	ns	1, 4, 6
T _{CLOV2}	RD, WR, GCS7:0, LCS, UCS, AD7:0, NCS, INTA1:0, S2:0, A15:8	3	27	ns	1, 4, 6
T _{CHOF}	RD, WR, RFSH, DT/R, LOCK, S2:0, A19:8	0	25	ns	1
T _{CLOF}	DEN, AD7:0, A15:8	0	25	ns	1
SYNCHRO	NOUS INPUTS				<u> </u>
T _{CHIS}	TEST, NMI, INT4:0, BCLK1:0, T1:0IN, READY, CTS1:0, P2.6, P2.7	10		ns	1, 9
T _{CHIH}	TEST, NMI, INT4:0, BCLK1:0, T1:0IN, READY, CTS1:0	3		ns	1, 9
T _{CLIS}	AD7:0, READY	10		ns	1, 10
T _{CLIH}	READY, AD7:0	3		ns	1, 10
T _{CLIS}	HOLD	10		ns	1, 9
T _{CLIH}	HOLD	3		ns	1, 9

- 1. See AC Timing Waveforms, for waveforms and definition.
- 2. Measure at V_{IH} for high time, V_{IL} for low time.
- 3. Only required to guarantee I_{CC}. Maximum limits are bounded by T_C, T_{CH} and T_{CL}.
- 4. Specified for a 50 pF load, see Figure 16 for capacitive derating information.
 5. Specified for a 50 pF load, see Figure 17 for rise and fall times outside 50 pF.
- 6. See Figure 17 for rise and fall times.
- 7. T_{CHOV1} applies to RFSH, LOCK and A19:8 only after a HOLD release.
- 8. T_{CHOV2} applies to RD and WR only after a HOLD release. 9. Setup and Hold are required to guarantee recognition.
- 10. Setup and Hold are required for proper 80C188EB operation.



AC Characteristics—80C188EB-13

Symbol	Parameter	Min	Max	Units	Notes
INPUT CL	оск			L	
T _F T _C T _{CH} T _{CL} T _{CR}	CLKIN Frequency CLKIN Period CLKIN High Time CLKIN Low Time CLKIN Rise Time	0 38.34 12 12	26.08	MHz ns ns ns	1 1 1,2 1,2 1,3
T _{CF}	CLKIN Fall Time	1	8	ns	1, 3
T _{CD} T T _{PH} T _{PL} T _{PR} T _{PF}	CLOCK CLKIN to CLKOUT Delay CLKOUT Period CLKOUT High Time CLKOUT Low Time CLKOUT Rise Time CLKOUT Fall Time	0 (T/2) - 5 (T/2) - 5	23 2*T _C (T/2) + 5 (T/2) + 5	ns ns ns ns	1, 4 1 1 1 1, 5
OUTPUT [1	6	ns	1, 5
Тсноv1	ALE, S2:0, DEN, DT/R, RFSH, LOCK, A19:16	3	25	ns	1, 4, 6, 7
T _{CHOV2}	GCS0:7, LCS, UCS, RD, WR	3	30	ns	1, 4, 6, 8
T _{CLOV1}	RFSH, DEN, LOCK, RESOUT, HLDA, TOOUT, T1OUT, A19:16	3	25	ns	1, 4, 6
T _{CLOV2}	RD, WR, GCS7:0, LCS, UCS, AD7:0, NCS, INTA1:0, \$2:0, A15:8	3	30	ns	1, 4, 6
T _{CHOF}	RD, WR, RFSH, DT/R, LOCK, S2:0, A19:16	0	25	ns	1
T _{CLOF}	DEN, AD7:0, A15:8	0	25	ns	1
SYNCHRO	NOUS INPUTS				4
T _{CHIS}	TEST, NMI, INT4:0, BCLK1:0, T1:0IN, READY, CTS1:0, P2.6, P2.7	10		ns	1, 9
T _{CHIH}	TEST, NMI, INT4:0, BCLK1:0, T1:0IN, READY, CTS1:0	3	. ,	ns	1, 9
T _{CLIS}	AD7:0, READY	10		ns	1, 10
T _{CLIH}	READY, AD7:0	3		ns	1, 10
T _{CLIS}	HOLD	10		ns	1, 9
T _{CLIH}	HOLD	3		ns	1, 9

NOTES:

- 1. See AC Timing Waveforms, for waveforms and definition.
- 2. Measure at V_{IH} for high time, V_{IL} for low time.
- 3. Only required to guarantee ICC. Maximum limits are bounded by T_C, T_{CH} and T_{CL}.
- Specified for a 50 pF load, see Figure 16 for capacitive derating information.
 Specified for a 50 pF load, see Figure 17 for rise and fall times outside 50 pF.
- 6. See Figure 17 for rise and fall times.
- 7. T_{CHOV1} applies to RFSH, LOCK and A8:0 only after a HOLD release.
- 8. T_{CHOV2} applies to RD and WR only after a HOLD release.
- 9. Setup and Hold are required to guarantee recognition.
- 10. Setup and Hold are required for proper 80C188EB operation.



AC Characteristics—80C188EB-8

Symbol	Parameter	Min	Max	Units	Notes		
INPUT CL	INPUT CLOCK						
T _F T _C	CLKIN Frequency CLKIN Period	0 62.5	16 ∞	MHz ns	1 1		
TCH	CLKIN High Time	15	∞	ns	1, 2		
T _{CL}	CLKIN Low Time	15	∞	ns	1, 2		
TCR	CLKIN Rise Time	1	8	ns	1, 3		
T _{CF}	CLKIN Fall Time	1	8	ns	1, 3		
OUTPUT (CLOCK						
T _{CD}	CLKIN to CLKOUT Delay	0	27	пѕ	1, 4		
T	CLKOUT Period		2*T _C	ns	1		
T _{PH}	CLKOUT High Time	(T/2) - 5	(T/2) + 5	ns	1		
T _{PL}	CLKOUT Low Time CLKOUT Rise Time	(T/2) - 5	(T/2) + 5	ns	1		
T _{PR} T _{PF}	CLKOUT Fall Time	1 1	6	ns	1, 5		
		1	6	ns	1, 5		
OUTPUT	,	,					
Тсноv1	ALE, \$2:0, \$\overline{\text{DEN}}, \text{DT/R}, \text{RFSH}, \$\overline{\text{LOCK}}, \text{A19:16}\$	3	30	ns	1, 4, 6, 7		
T _{CHOV2}	GCS0:7, LCS, UCS, RD, WR	3	35	ns	1, 4, 6, 8		
T _{CLOV1}	RFSH, DEN, LOCK, RESOUT, HLDA, TOOUT, T1OUT, A19:16	3	30	ns	1, 4, 6		
T _{CLOV2}	RD, WR, GCS7:0, LCS, UCS, AD7:0, NCS, INTA1:0, S2:0, A15:8	3	35	ns	1, 4, 6		
TCHOF	RD, WR, RFSH, DT/R, LOCK, S2:0, A19:16	0	30	ns	. 1		
T _{CLOF}	DEN, AD7:0, A15:8	0	35	ns	1		
SYNCHRO	NOUS INPUTS						
T _{CHIS}	TEST, NMI, INT4:0, BCLK1:0 T1:0IN, READY, CTS1:0, P2.6, P2.7	10		ns	1, 9		
T _{CHIH}	TEST, NMI, INT4:0, BCLK1:0 T1:0IN, READY, CTS1:0	3		ns	1, 9		
T _{CLIS}	AD7:0, READY	10		ns	1, 10		
T _{CLIH}	READY, AD7:0	3		ns	1, 10		
T _{CLIS}	HOLD	10		ns	1, 9		
T _{CLIH}	HOLD	3	-	ns	1, 9		

- 1. See AC Timing Waveforms, for waveforms and definition.
- 2. Measure at V_{IH} for high time, V_{IL} for low time.

 3. Only required to guarantee I_{CC}. Maximum limits are bounded by T_C, T_{CH} and T_{CL}.

 4. Specified for a 50 pF load, see Figure 16 for capacitive derating information.

 5. Specified for a 50 pF load, see Figure 17 for rise and fall times outside 50 pF.

- 6. See Figure 17 for rise and fall times.
 7. T_{CHOV1} applies to RFSH, LOCK and A19:8 only after a HOLD release.
- 8. T_{CHOV2} applies to RD and WR only after a HOLD release.
- 9. Setup and Hold are required to guarantee recognition.
- 10. Setup and Hold are required for proper 80C188EB operation.



Relative Timings (80C188EB-16, -13, -8)

Symbol	Parameter	Min	Max	Unit	Notes
RELATIVE	TIMINGS				
TLHLL	ALE Rising to ALE Falling	T - 15		ns	
TAVLL	Address Valid to ALE Falling	½T - 10		ns	
T _{PLLL}	Chip Selects Valid to ALE Falling	½T - 10		ns	1
T _{LLAX}	Address Hold from ALE Falling	½T – 10		ns	
T _{LLWL}	ALE Falling to WR Falling	½T - 15		ns	1
T _{LLRL}	ALE Falling to RD Falling	· ½T – 15		ns	1
TWHLH	WR Rising to ALE Rising	½T - 10		ns	1
TAFRL	Address Float to RD Falling	0		ns	
T _{RLRH}	RD Falling to RD Rising	(2*T) - 5		ns	2 •
T _{WLWH}	WR Falling to WR Rising	(2*T) - 5		ns	2
T _{RHAV}	RD Rising to Address Active	T — 15		ns	
T _{WHDX}	Output Data Hold after WR Rising	T – 15		ns	
T _{WHPH}	WR Rising to Chip Select Rising	½T — 10		ns	1
TRHPH	RD Rising to Chip Select Rising	½T – 10		ns	1
T _{PHPL}	CS Inactive to CS Active	½T - 10		ns	1
Tovrh	ONCE Active to RESIN Rising	Т		ns	3
T _{RHOX}	ONCE Hold from RESIN Rising	Т		ns	3

Assumes equal loading on both pins.
 Can be extended using wait states.
 Not tested.



Serial Port Mode 0 Timings (80C188EB-16, -13, -8)

Symbol	Parameter	Min	Max	Unit	Notes
T_{XLXL}	TXD Clock Period	T (n + 1)		ns	1, 2
T_{XLXH}	TXD Clock Low to Clock High (n > 1)	2T - 35	2T + 35	ns	1
T _{XLXH}	TXD Clock Low to Clock High (n = 1)	T - 35	T + 35	ns	1
T_{XHXL}	TXD Clock High to Clock Low (n > 1)	(n - 1) T - 35	(n - 1) T + 35	ns	1, 2
T _{XHXL}	TXD Clock High to Clock Low (n = 1)	T - 35	T + 35	ns	1
T _{QVXH}	RXD Output Data Setup to TXD Clock High (n > 1)	(n - 1) T - 35	7	ns	1, 2
T_{QVXH}	RXD Output Data Setup to TXD Clock High (n = 1)	T - 35		ns	1
T _{XHQX}	RXD Output Data Hold after TXD Clock High (n > 1)	2T - 35		ns	1
T _{XHQX}	RXD Output Data Hold after TXD Clock High (n = 1)	T - 35	-	ns	1
T _{XHQZ}	RXD Output Data Float after Last TXD Clock High		T + 20	ns	<u>-</u> _
T _{DVXH}	RXD Input Data Setup to TXD Clock High	T + 20		ns	<u>-</u>
T _{XHDX}	RXD Input Data Hold after TXD Clock High	0		ns	1

NOTES:

^{1.} See Figure 15 for waveforms.

^{2.} n is the value of the BxCMP register ignoring the iCLK bit (i.e., ICLK = 0).



AC TEST CONDITIONS

The AC specifications are tested with the 50 pF load shown in Figure 10. See the Derating Curves section to see how timings vary with load capacitance.

Specifications are measured at the $V_{\rm CC}/2$ crossing point, unless otherwise specified. See AC Timing Waveforms, for AC specification definitions, test pins, and illustrations.

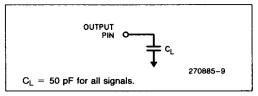


Figure 10. AC Test Load

AC TIMING WAVEFORMS

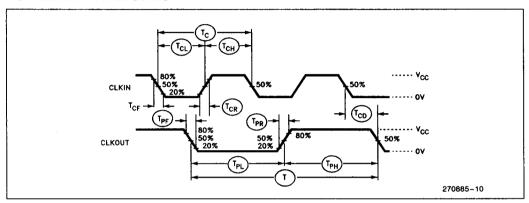


Figure 11. Input and Output Clock Waveform

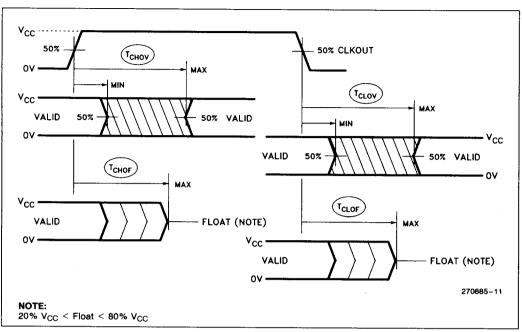


Figure 12. Output Delay and Float Waveform

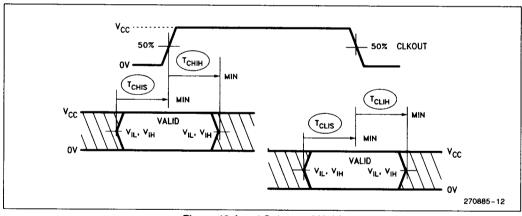


Figure 13. Input Setup and Hold

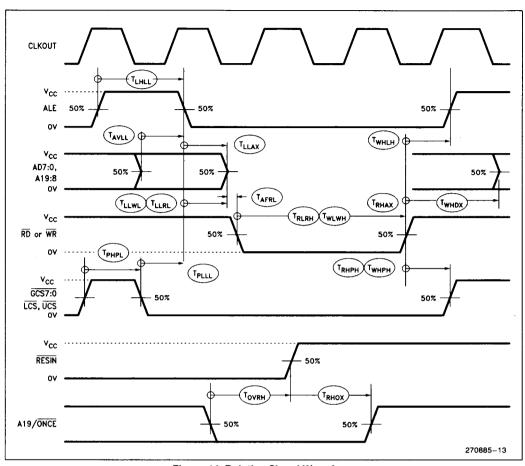


Figure 14. Relative Signal Waveform

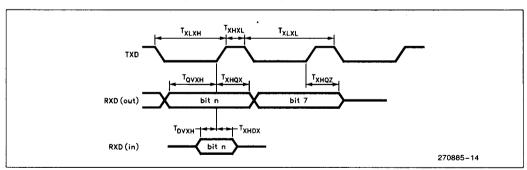


Figure 15. Serial Port Mode 0 Waveform

DERATING CURVES

TYPICAL OUTPUT DELAY VARIATIONS VERSUS LOAD CAPACITANCE

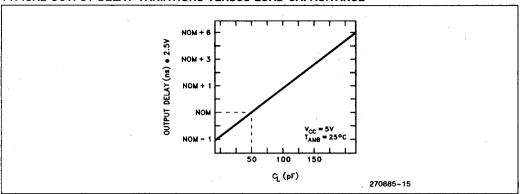


Figure 16

TYPICAL RISE AND FALL VARIATIONS VERSUS LOAD CAPACITANCE

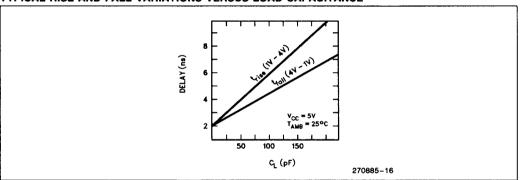


Figure 17

RESET

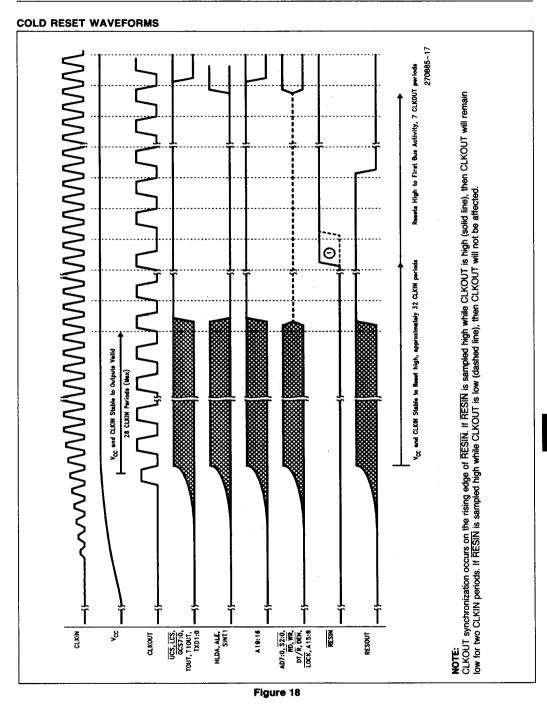
The 80C188EB will perform a reset operation any time the RESIN pin active. The RESIN pin is actually synchronized before it is presented internally, which means that the clock must be operating before a reset can take effect. From a power-on state, RESIN must be held active (low) in order to guarantee correct initialization of the 80C188EB. Fallure to provide RESIN while the device is powering up will result in unspecified operation of the device.

Figure 18 shows the correct reset sequence when first applying power to the 80C188EB. An external clock connected to CLKIN must not exceed the V_{CC} threshold being applied to the 80C188EB. This is normally not a problem if the clock driver is supplied with the same V_{CC} that supplies the 80C188EB. When attaching a crystal to the device, $\overline{\text{RESIN}}$ must remain active until both V_{CC} and CLKOUT are stable (the length of time is application specific and depends on the startup characteristics of the crystal circuit). The $\overline{\text{RESIN}}$ pin is designed to operate correctly using an RC reset circuit, but the designer

must ensure that the ramp time for V_{CC} is not so long that \overline{RESIN} is never really sampled at a logic low level when V_{CC} reaches minimum operating conditions.

Figure 19 shows the timing sequence when $\overline{\text{RESIN}}$ is applied after V_{CC} is stable and the device has been operating. Note that a reset will terminate all activity and return the 80C188EB to a known operating state. Any bus operation that is in progress at the time $\overline{\text{RESIN}}$ is asserted will terminate immediately (note that most control signals will be driven to their inactive state first before floating).

While RESIN is active, bus signals LOCK, A19/ONCE, and A18:16 are configured as inputs and weakly held high by internal pullup transistors. Only 19/ONCE can be overdriven to a low and is used to enable ONCE Mode. Forcing LOCK or A18:16 low at any time while RESIN is low is prohibited and will cause unspecified device operation.



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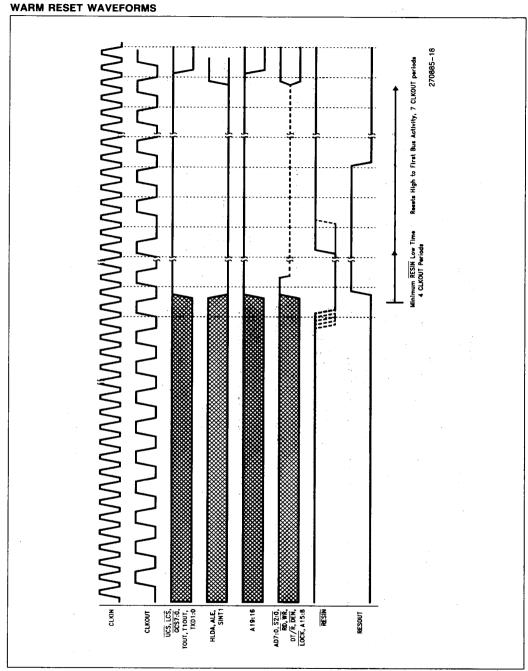


Figure 19

24-796

BUS CYCLE WAVEFORMS

Figures 20 through 26 present the various bus cycles that are generated by the 80C188EB. What is shown in the figure is the relationship of the various bus signals to CLKOUT. These figures along with the information present in **AC Specifications** allow the user to determine all the critical timing analysis needed for a given application.

Figure 20 shows the 80C188EB bus state diagram. A typical bus cycle will consist of four consecutive states labeled T1, T2, T3, and T4. A TI state exists when no bus cycle is pending. A TI state can occur if the pre-fetch queue is full, the BIU is waiting for the completion of an effective address calculation, or the BIU is told to wait for a pending EU bus operation. The latter case will occur most often during the sequencing of an interrupt acknowledge.

Aside from TI states, multiple T3 states can occur during a bus cycle if READY is not returned in time (or the CSU has been programmed to automatically insert wait-states). A T3 state will be followed by either a T4 state (if a bus cycle is pending), or a TI state (if no bus cycle is pending). Only multiple T3 or TI states can exist (i.e., there is no way to extend the T1, T2, or T4 states).

Figures 21 and 22 present a typical bus read and write operation respectively. Bus read operations include memory, I/O, instruction fetch, and refresh bus cycles. Bus write operations include memory and I/O bus cycles. The only variation among the

different bus cycles would be the range of address generated and the state of the status signals.

The Halt bus cycle is shown in Figure 23. Note that the condition of the AD7:0 pin can be either floating or driving depending on the operation of the bus cycle that preceded the Halt. The pins will float if the previous bus cycle was a read, otherwise they will drive. None of the control signals (e.g., $\overline{\text{RD}}$, $\overline{\text{WR}}$, $\overline{\text{DEN}}$, etc.) will be activated, however.

Figure 24 shows the sequence of bus cycles run when an interrupt is acknowledged and the ICU has been programmed for Cascade Mode. Note the address information is not valid for the two bus cycles run, however, also note that $\overline{\text{RD}}$ and $\overline{\text{WR}}$ are not generated. Vector information needs to be returned during the second bus cycle.

Figures 25 and 26 present the operation of bus HOLD. Figure 25 shows how bus HOLD is entered and exited under normal operating conditions. Figure 26 shows the effect specific bus signals have when a refresh bus cycle request has been generated and the bus is currently unavailable due to a bus HOLD.

The effects of READY on bus operation is shown in Figure 27. READY is useful in extending the bus cycle to meet the various access requirements for memory and peripheral devices in the system. Additional T3 states added to the bus cycle have been appropriately labeled Tw.

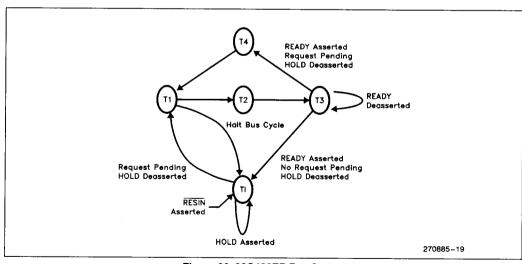


Figure 20. 80C188EB Bus States



BUS CYCLE WAVEFORMS

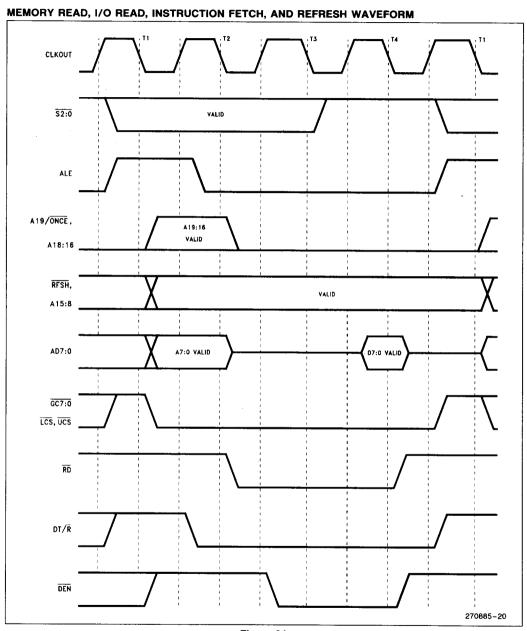
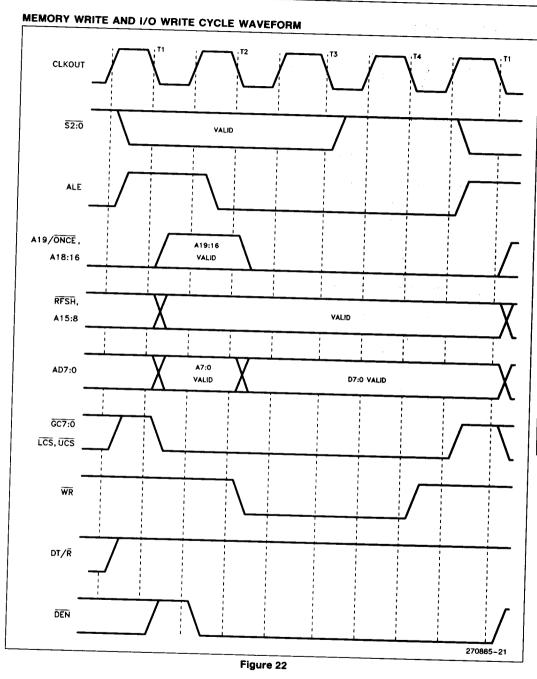


Figure 21

24-798



24-799



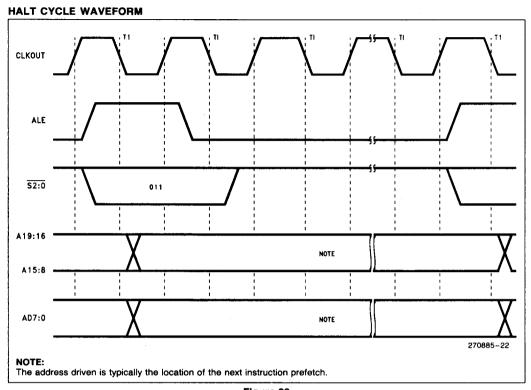
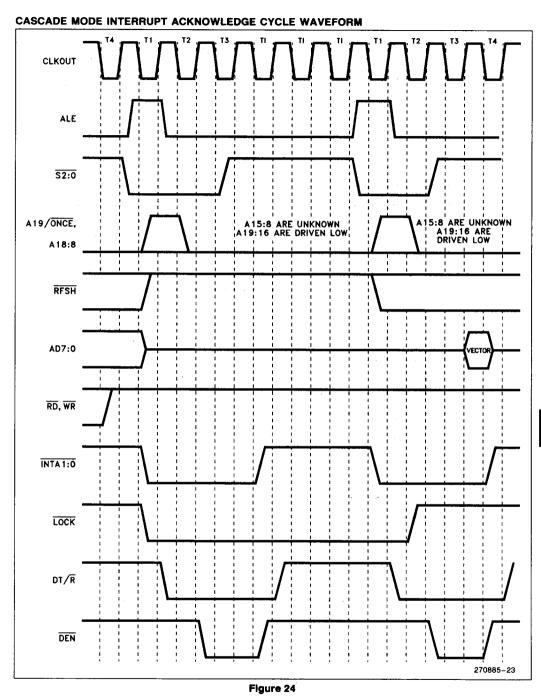


Figure 23





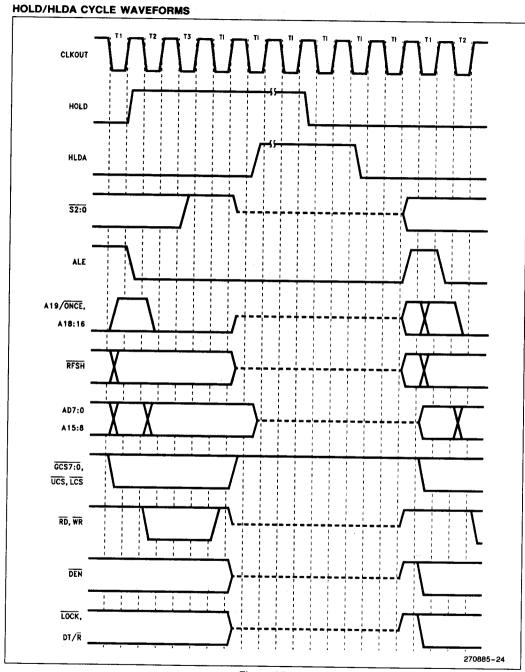
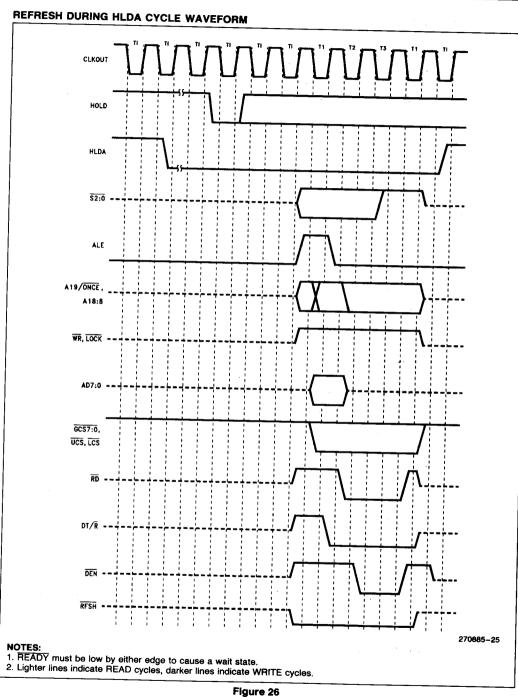


Figure 25

24-802





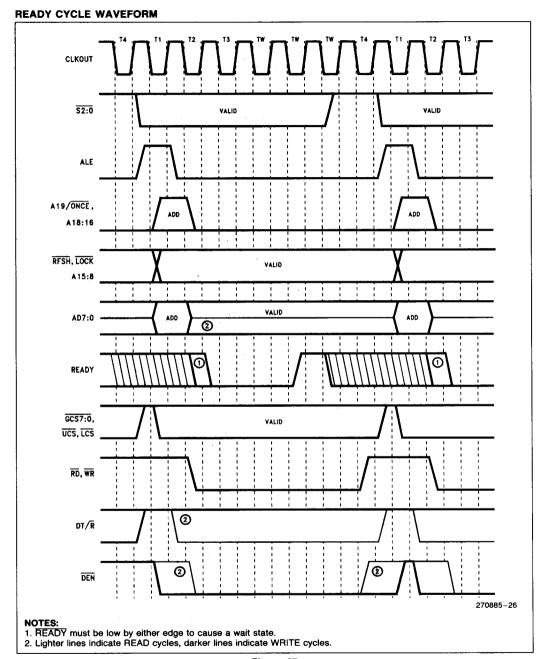


Figure 27

24-804

REGISTER BIT SUMMARY

Figures 28 through 35 present the bit definition of each register that is active (not reserved) in the Peripheral Control Block (PCB). Each register can be thought to occupy one word (16-bits) of either memory or I/O space, although not all bits in the register necessarily have a function. A register bit is not guaranteed to return a specific logic value if an "X" appears for the bit definition (i.e., if a zero was written to the register bit it may not be returned as a zero when read). Furthermore, a 0 must be written to any bit that is indicated by an "X" to ensure compatibility with future products or potential product changes.

Not all defined register bits can be read and/or written, although most registers are read/write. Some registers, like the P1DIR register, exist but do not have any effect on the operation of the 80C188EB. For example, the Port1 pins are output only and cannot be changed by programming the P1DIR register. However, the P1DIR register can still be read and written—which allows the P1DIR register to be used as a temporary 8-bit data register.

Reads and writes to any of the PCB registers will cause a bus cycle to be run externally, however, none of the chip selects will go active (even if they overlap the PCB address range). Data read back from the AD7:0 bus is ignored, and all cycles will take zero wait states (except accesses to the Timer/Counter registers which take one wait state due to internal synchronization).

Figures 28 and 29 present the registers associated with the Interrupt Control Unit (ICU). A write to the MASK (08H) register will also effect the corresponding MSK bit in each of the control registers (e.g., setting the TMR bit in the MASK register will also set the MSK bit in the TMRCON register).

The Timer/Counter Unit registers are presented in Figure 30. The compare and count registers are **not** initialized after reset and must be set correctly during initialization to ensure the timer operates correctly the first time it is enabled.

Figure 31 presents the I/O Port UNIT (IPU) registers. Only PD6 and PD7 or of the P2DIR register have any effect on the direction of the port pins (P2.6 and P2.7 respectively). The unused bits of P2DIR and all the bits of P1DIR can be thought of having latches that can be read and written. The two PxLTCH registers have all 8-bits implemented, however, only those port pins which can function as outputs actually use the value programmed into the latch. Otherwise (like the P1DIR register), the registers can be thought of being an 8-bit data register.

Figure 32 presents the register bit definitions of the Serial Communications Unit (SCU). The transmit and receive buffer registers are both readable and writeable. Note that a read from SxSTS register will clear all of the status information (except for CTS, which actually is derived from the pin itself).

The Chip-Select Unit (CSU) registers are presented in Figure 33 and the Refresh Control Unit (RCU) registers are presented in Figure 34. The RFADDR register will indicate the current refresh address when read, and a write to the register will change the next refresh address generated.

Figure 35 presents the PWRCON register and STEPID register. The STEPID register contains a stepping identifier that may or may not change any time there is a change to the 80C188EB silicon die. The STEPID is for Intel use and can change at any time.

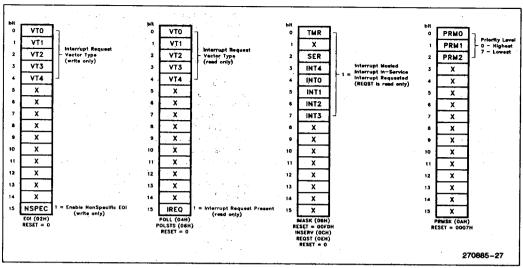


Figure 28. Interrupt Control Unit Registers

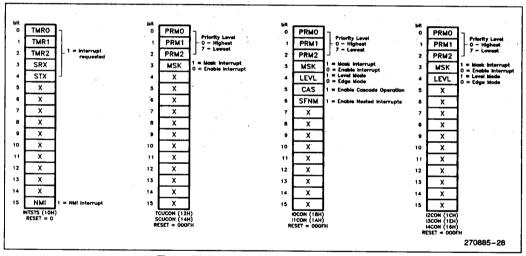


Figure 29. Interrupt Control Unit Registers

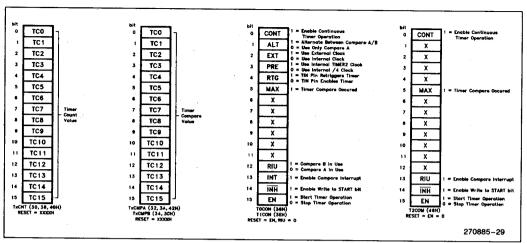


Figure 30. Timer Control Unit Registers

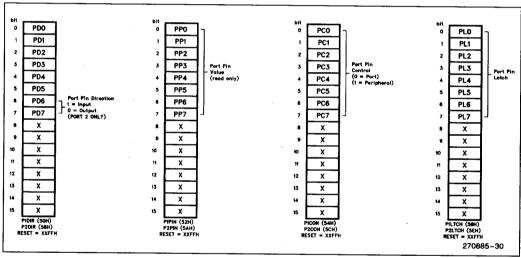


Figure 31. I/O Port Unit Registers

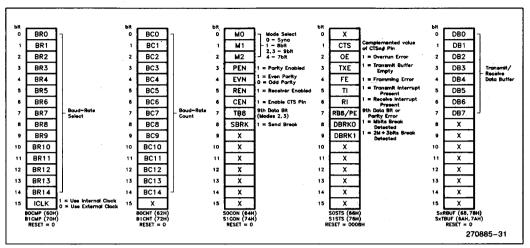


Figure 32. Serial Communications Unit Registers

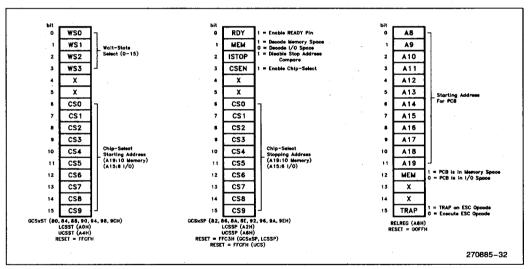


Figure 33. Chip-Select Unit Registers

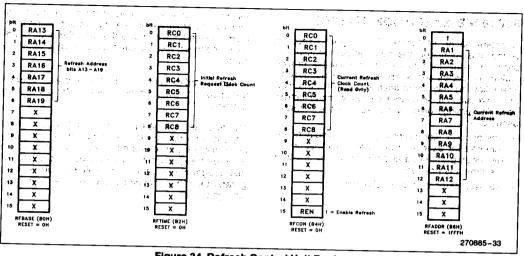


Figure 34. Refresh Control Unit Registers

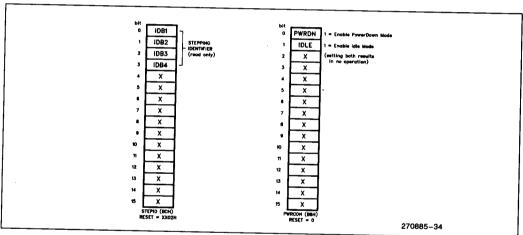


Figure 35. Power Management Unit Registers



80C188EB EXECUTION TIMINGS

A determination of 80C188EB program execution timing must consider the bus cycles necessary to prefetch instructions as well as the number of execution unit cycles necessary to execute instructions. The following instruction timings represent the minimum execution time in clock cycles for each instruction. The timings given are based on the following assumptions:

- The opcode, along with any data or displacement required for execution of a particular instruction, has been prefetched and resides in the queue at the time it is needed.
- · No wait states or bus HOLDs occur.

All instructions which involve memory accesses can require one or two additional clocks above the minimum timings shown due to the asynchronous handshake between the bus interface unit (BIU) and execution unit.

All jumps and calls include the time required to fetch the opcode of the next instruction at the destination address.

The 80C188EB 8-bit BIU is noticeably limited in its performance relative to the execution unit. A sufficient number of prefetched bytes may not reside in the prefetch queue much of the time. Therefore, actual program execution time will be substantially greater than that derived from adding the instruction timings shown.

INSTRUCTION SET SUMMARY

Function		Fo	rmat		Clock Cycles	Comments
DATA TRANSFER MOV = Move:						
Register to Register/Memory	1000100w	mod reg r/m			2/12	
Register/memory to register	1000101w	mod reg r/m			2/9	
Immediate to register/memory	1100011w	mod 000 r/m	data	data if w = 1	12-13	8/16-bit
Immediate to register	1011w reg	data	data if w = 1		3-4	8/16-bit
Memory to accumulator	1010000w	addr-low	addr-high		8	
Accumulator to memory	1010001w	addr-low	addr-high		9	
Register/memory to segment register	10001110	mod 0 reg r/m			2/9	
Segment register to register/memory	10001100	mod 0 reg r/m			2/11	
PUSH = Push:						
Memory	1111111	mod 1 1 0 r/m			16	
Register	01010 reg				10	
Segment register	0 0 0 reg 1 1 0				9	
Immediate	011010s0	data	data if s = 0		10	
PUSHA = Push Ali	01100000					
POP = Pop:	0110000	l			36	
Memory	10001111	mod 0 0 0 r/m			20	
Register	01011 reg				10	
Segment register	0 0 0 reg 1 1 1	(reg≠01)			8	i I
POPA = Pop Ali	01100001				51	
XCHG = Exchange:					5,	
Register/memory with register	1000011w	mod reg r/m			4/17	
Register with accumulator	10010 reg				3	
IN = Input from:						
Fixed port	1110010w	port			10	
Variable port	1110110w				8	
OUT = Output to:						
Fixed port	1110011w	port			9	
Variable port	1110111w				7	
XLAT = Translate byte to AL	11010111				11	
LEA = Load EA to register	10001101	mod reg_r/m			6	
LDS = Load pointer to DS	11000101	mod reg r/m	(mod≠11)		18	
LES = Load pointer to ES	11000100	mod reg r/m	(mod≠11)		18	
LAHF = Load AH with flags	10011111				2	
SAHF = Store AH into flags	10011110				3	
PUSHF = Push flags	10011100				9	
POPF = Pop flags	10011101				8	
Shaded areas indicate instructions	not available is	0000/0000:-				



Function		For	rmat		Clock Cycles	Comments
DATA TRANSFER (Continued)						
SEGMENT = Segment Override: CS	00101110				2	
SS	00110110				2	
DS ·	00111110	-			2	
ES					2	
es Arithmetic	00100110	-			*	
ADD = Add:				•		
Reg/memory with register to either	000000dw	mod reg r/m			3/10	
Immediate to register/memory	100000sw	mod 0 0 0 r/m	data	data if s w = 01	4/16	
Immediate to accumulator	0000010w	data	data if w = 1		3/4	8/16-bit
ADC = Add with carry:		<u> </u>				
Reg/memory with register to either	000100dw	mod reg r/m			3/10	
Immediate to register/memory	100000sw	mod 0 1 0 r/m	data	data if s w = 01	4/16	
Immediate to accumulator	0001010w	data	data if w = 1	1	3/4	8/16-bit
INC = Increment:						
Register/memory	1111111w	mod 0 0 0 r/m			3/15	
Register	01000 reg	"			3	
SUB = Subtract:	•					
Reg/memory and register to either	001010dw	mod reg r/m			3/10	
Immediate from register/memory	100000sw	mod 1 0 1 r/m	data	data if s w = 01	4/16	
Immediate from accumulator	0010110w	data	data if w = 1		3/4	8/16-bit
SBB = Subtract with borrow:		:		•	ļ	İ
Reg/memory and register to either	000110dw	mod reg r/m			3/10	
Immediate from register/memory	100000sw	mod 0 1 1 r/m	data	data if s w=01	4/16	İ
Immediate from accumulator	0001110w	data	data if w = 1]	3/4	8/16-bit
DEC = Decrement				•		
Register/memory	11111111W	mod 0 0 1 r/m			3/15	1
Register	01001 reg]			3	
CMP = Compare:						
Register/memory with register	0011101w	mod reg r/m			3/10	
Register with register/memory	0011100w	mod reg r/m			3/10	
Immediate with register/memory	100000sw	mod 1 1 1 r/m	data	data if s w = 01	3/10	
Immediate with accumulator	0011110w	data	data if w = 1]	3/4	8/16-bit
NEG = Change sign register/memory	1111011w	mod 0 1 1 r/m			3/10	
AAA = ASCII adjust for add	00110111	,			8	
DAA = Decimal adjust for add	00100111	ĺ			4	
AAS = ASCII adjust for subtract	00111111	i			7	
DAS = Decimal adjust for subtract	00101111	า์			4	1
•		1	ì			1
MUL = Multiply (unsigned):	1111011w	mod 100 r/m	l		20.00	
Register-Byte Register-Word			-		26-28 35-37	
Memory-Byte Memory-Word	*				32-34 41-43	

Shaded areas indicate instructions not available in 8086/8088 microsystems.

Function		Fo	rmat		Clock Cycles	Comments
ARITHMETIC (Continued)						
IMUL = Integer multiply (signed): Register-Byte Register-Word Memory-Byte Memory-Word	1111011w	mod 1 0 1 r/m	}		25-28 34-37 31-34 40-43	
IMUL = Integer Immediate multiply (signed)	011010s1	mod reg_r/m	data	data if s = 0	22-25/ 29-32	
DIV = Divide (unsigned):	1111011w	mod 1 1 0 r/m				
Register-Byte Register-Word Memory-Byte Memory-Word					29 38 35 44	
IDIV = Integer divide (signed):	1111011w	mod 1 1 1 r/m				
Register-Byte Register-Word Memory-Byte Memory-Word					44-52 53-61 50-58 59-67	,
AAM = ASCII adjust for multiply	11010100	00001010			19	
AAD = ASCII adjust for divide	11010101	00001010			15	
CBW = Convert byte to word	10011000]			2	
CWD = Convert word to double word	10011001]			4	
LOGIC Shift/Rotate Instructions:						
Register/Memory by 1	1101000w	mod TTT r/m			2/15	
Register/Memory by CL	1101001w	mod T∏ r/m			5+n/17+n	
Register/Memory by Count	1100000w	mod TTT r/m	count		5+n/17+n	
AND = And:		TTT Instruction 0 0 0 ROL 0 0 1 ROR 0 1 0 RCL 0 1 1 RCR 1 0 0 SHL/SAL 1 0 1 SAR				
Reg/memory and register to either	001000dw	mod reg r/m			3/10	
Immediate to register/memory	1000000w	mod 1 0 0 r/m	data	data if w = 1	4/16	
Immediate to accumulator	0010010w	data	data if w = 1		3/4	8/16-bit
TEST = And function to flags, no resu	ult:	,	ı			
Register/memory and register	1000010w	mod reg r/m			3/10	
Immediate data and register/memory	1111011w	mod 0 0 0 r/m	data	data if w = 1	4/10	
Immediate data and accumulator	1010100w	data	data if w = 1		3/4	8/16-bit
OR = Or:		,	1			
Reg/memory and register to either	000010dw	mod reg r/m			3/10	
Immediate to register/memory	1000000w	mod 0 0 1 r/m	data	data if w = 1	4/16	
Immediate to accumulator	0000110w	data	data if w = 1		3/4	8/16-bit



Function	Format					Comments
LOGIC (Continued) XOR = Exclusive or:					Cycles	
Reg/memory and register to either	001100dw	mod reg r/m			3/10	
Immediate to register/memory	1000000w	mod 1 1 0 r/m	data	data if w = 1	4/16	
Immediate to accumulator	0011010w	data	data if w = 1		3/4	8/16-bit
NOT = Invert register/memory	1111011w	mod 0 1 0 r/m			3/10	
STRING MANIPULATION		,				
MOVS = Move byte/word	1010010w				14	
CMPS = Compare byte/word	1010011w				22	
SCAS = Scan byte/word	1010111w]			15	
LODS = Load byte/wd to AL/AX	1010110w]			12	
STOS = Store byte/wd from AL/AX	1010101w].			10	
INS = Input byte/wd from DX port	0110110w]			14	
OUTS = Output byte/wd to DX port	0110111w]			14	
Repeated by count in CX (REP/REPE/	REPZ/REPNE/REP	'NZ)				
MOVS Move string	11110010	1010010w			8 + 8n	
CMPS = Compare string	1111001z	1010011w			5 + 22n	
SCAS - Scan string	1111001z	1010111w			5 + 15n	
LODS :: Load string	11110010	1010110w			6+11n	
STOS = Store string	11110010	1010101w			6 + 9n	
INS = Input string	11110010	0110110w			8+8n	
OUTS = Output string	11110010	0110111w	1		8+8n	
CONTROL TRANSFER			1			
CALL = Call:						
Direct within segment	11101000	disp-low	disp-high		15	
Register/memory	1111111	mod 0 1 0 r/m			13/19	
indirect within segment						
Direct intersegment	10011010	segmen	nt offset		23	
		segment	selector			,
Indirect intersegment	1111111	mod 0 1 1 r/m	(mod ≠ 11)		38	
JMP = Unconditional jump:						
Short/long	11101011	disp-low			14	
Direct within segment	11101001	disp-low	disp-high		14	
Register/memory	11111111	mod 1 0 0 r/m	-	•	11/17	
indirect within segment			•			
Direct intersegment	11101010	segme	nt offset		14	
		segmen	selector			
Indirect intersegment	11111111	mod 1 0 1 r/m	(mod ≠ 11)		26	
Shaded areas indicate instruction			' '			1

Function		Format		Clock Cycles	Comments
CONTROL TRANSFER (Continued) RET = Return from CALL:					
Within segment	11000011]		16	
Within seg adding immed to SP	11000010	data-low	data-high	18	
Intersegment	11001011]	· · · · · · · · · · · · · · · · · · ·	22	
Intersegment adding immediate to SP	11001010	data-low	data-high	25	
JE/JZ = Jump on equal/zero	01110100	disp		4/13	JMP not
JL/JNGE = Jump on less/not greater or equal	01111100	disp		4/13	taken/JMP
JLE/JNG = Jump on less or equal/not greater	01111110	disp		4/13	taken
JB/JNAE = Jump on below/not above or equal	01110010	disp		4/13	
JBE/JNA = Jump on below or equal/not above	01110110	disp		4/13	
JP/JPE = Jump on parity/parity even	01111010	disp		4/13	
JO = Jump on overflow	01110000	disp		4/13	
JS = Jump on sign	01111000	disp		4/13	
JNE/JNZ = Jump on not equal/not zero	01110101	disp		4/13	
JNL/JGE = Jump on not less/greater or equal	01111101	disp		4/13	
JNLE/JG = Jump on not less or equal/greater	0111111	disp	*	4/13	
JNB/JAE = Jump on not below/above or equal	01110011	disp		4/13	
JNBE/JA = Jump on not below or equal/above	01110111	disp		4/13	
JNP/JPO = Jump on not par/par odd	01111011	disp		4/13	
JNO = Jump on not overflow	01110001	disp		4/13	
JNS = Jump on not sign	01111001	disp		4/13	
JCXZ ≕ Jump on CX zero	11100011	disp		5/15	
LOOP = Loop CX times	11100010	disp		6/16	LOOP not
LOOPZ/LOOPE = Loop while zero/equal	11100001	disp		6/16	taken/LOOP
LOOPNZ/LOOPNE = Loop while not zero/equal	11100000	disp		6/16	taken
ENTER = Enter Procedure	11001000	data-low	data-high L		
L = 0 L = 1 L > 1				15 25 22 + 16(n - 1)	
LEAVE = Leave Procedure	11001001			8	1
INT = Interrupt:				,	
Type specified	11001101	type		47	
Type 3	11001100			45	if INT. taken/
INTO = Interrupt on overflow	11001110			48/4	if INT, not taken
IRET = Interrupt return	11001111			28	
BOUND = Detect value out of range	01100010	mod reg r/m		33-35	

Function	Format	Clock Cycles	Comments
PROCESSOR CONTROL			Ī
CLC = Clear carry	11111000	2	
CMC = Complement carry	11110101	2	
STC = Set carry	11111001	2	
CLD = Clear direction	11111100	2	
STD = Set direction	1111101	2	
CLI = Clear interrupt	11111010	2	1
STI = Set interrupt	11111011	2	
HLT = Halt	11110100	2	
WAIT = Wait	10011011	6	if TEST = 0
LOCK = Bus lock prefix	11110000	2	
NOP = No Operation	10010000	3	
	(TTT LLL are opcode to processor extension)		

Shaded areas indicate instructions not available in 8086/8088 microsystems.

FOOTNOTES

The Effective Address (EA) of the memory operand is computed according to the mod and r/m fields:

uteu	according to the mod and irin neigs.
=	11 then r/m is treated as a REG field
=	00 then DISP = $0*$, disp-low and disp
	high are absent
=	01 then DISP = disp-low sign-ex-
	tended to 16-bits, disp-high is absent
==	10 then DISP = disp-high: disp-low
=	000 then $EA = (BX) + (SI) + DISP$
=	001 then EA = $(BX) + (DI) + DISP$
=	010 then EA = $(BP) + (SI) + DISP$
=	011 then EA = $(BP) + (DI) + DISP$
=	100 then EA = $(SI)' + DISP$
=	101 then EA = (DI) + DISP
=	110 then EA = $(BP) + DISP*$
=	111 then $EA = (BX) + DISP$

DISP follows 2nd byte of instruction (before data if required)

EA calculation time is 4 clock cycles for all modes, and is included in the execution times given whenever appropriate.

Segment Override Prefix

0	0	1	reg	1	1	0

reg is assigned according to the following:

	Segment
reg	Register
00	ES
01	CS
10	SS
11	DS

REG is assigned according to the following table:

8-Bit (w = 0
000 AL
001 CL
010 DL
011 BL
100 AH
101 CH
110 DH
111 BH

The physical addresses of all operands addressed by the BP register are computed using the SS segment register. The physical addresses of the destination operands of the string primitive operations (those addressed by the DI register) are computed using the ES segment, which may not be overridden.

^{*}except if mod = 00 and r/m = 110 then EA = disp-high: disp-low.

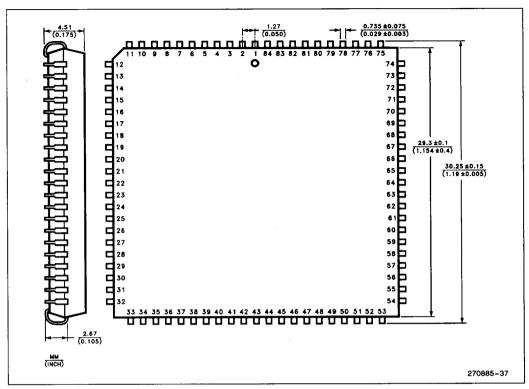


Figure 36. PLCC Principal Dimensions

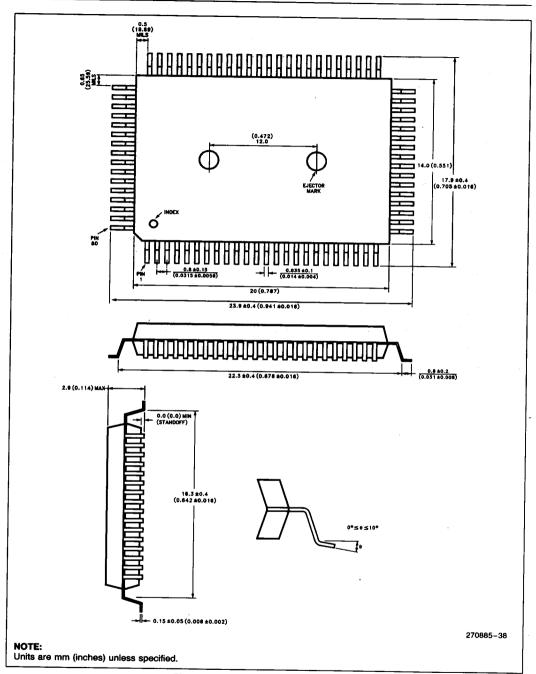


Figure 37. QFP Principal Dimensions

ERRATA

An 80C188EB with a STEPID value of 0001H has the following known errata. A device with a STEPID of 0001H can be visually identified by noting the absence of an alpha character next to the FPO number or by the **presence** of an "A" alpha character next to the FPO number. The FPO number location is shown in Figures 8 and 9.

- 1. A19/ONCE is not latched by the rising edge of RESIN. A19/ONCE must remain active (LOW) at all times to remain in the ONCE™ Mode. Removing A19/ONCE after RESIN is high will return all output pins to a driving state, however, the 80C188EB will remain in a reset state.
- 2. During interrupt acknowledge (INTA) bus cycles, the bus controller will ignore the state of the READY pin if the previous bus cycle ignored the state of the READY pin. This errata can only occur if the Chip-Select Unit is being used. All active chip-selects must be programmed to use READY (RDY bit must be programmed to a 1) if waitstates are required for INTA bus cycles.
- CLKOUT will transition off the rising edge of CLKIN rather than the falling edge of CLKIN. This does not affect any bus timings other than T_{CICO}.
- RESIN has a hysterisis of only 130 mV. It is recommended that RESIN be driven with a Schmitt triggered device to avoid processor lockup during reset when using an RC circuit.
- 5. SINT1 will only go active for one clock period when a receive or transmit interrupt is pending (i.e., it does not remain active until the S1STS register is read). If SINT1 is to be connected to any of the 80C188EB interrupt lines (INT0-INT4), then it must be latched by user logic.

An 80C188EB with a STEPID value of 0002H has no known errata (as of this publication). A device with a STEPID value of 0002H can be visually identified by locating the "B" alpha character next to the FPO number. The FPO number location is shown in Figures 8 and 9.

REVISION HISTORY

The following changes have been made between the -001 version and this (-002) version of the 80C188EB data sheet. This -002 data sheet applies to any 80C188EB with a "B" alpha character after the FPO number. The FPO number location is shown in Figures 8 and 9.

- The data sheet was changed from a Product Preview version to an Advanced Information version.
- Figures 1, 8, 9, 11, 15, 21, 23, 24, 25, 26, 27, 33, and 35 and Table 4 were updated to correct for errors.
- The DC specifications table has changed. Also, notes 3, 4 and 5 have been changed/added.
- Graphs for I_{CC} versus Frequency have been changed to equations with supporting text.
- Graphs for PDTMR pin capacitance have been changed to equations with supporting text.
- AC Hold timings have been changed from 0 ns to 3 ns.
- 7. READY input setup time has been changed from 13 ns to 10 ns.
- 8. Serial port MODE 0 timings have been changed.
- Various typing errors have been corrected throughout the document.

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